DSP56007

SYMPHONYTM AUDIO DSP FAMILY 24-BIT DIGITAL SIGNAL PROCESSORS

Motorola designed the Symphony[™] family of high-performance, programmable Digital Signal Processors (DSPs) to support a variety of digital audio applications, including Dolby ProLogic, ATRAC, and Lucasfilm Home THX processing. Software for these applications is licensed by Motorola for integration into products like audio/video receivers, televisions, and automotive sound systems with such user-developed features as digital equalization and sound field processing. The DSP56007 is an MPU-style general purpose DSP, composed of an efficient 24-bit Digital Signal Processor core, program and data memories, various peripherals optimized for audio, and support circuitry. As illustrated in **Figure 1**, the DSP56000 core family compatible DSP is fed by program memory, two independent data RAMs and two data ROMs, a Serial Audio Interface (SAI), Serial Host Interface (SHI), External Memory Interface (EMI), dedicated I/O lines, on-chip Phase Lock Loop (PLL), and On-Chip Emulation (OnCETM) port. The DSP56007 has significantly more on-chip memory than the DSP56004.

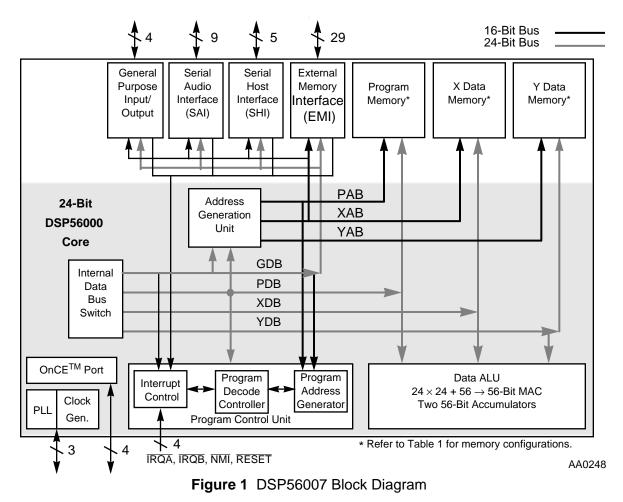




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Data Sheet Conventions

This data sheet uses the following conventions:

OVERBAR	Used to indicate a signal that is active when pulled low (For example, the $\overline{\text{RESET}}$ pin is active when low.)				
"asserted"	Means that a high true is low	Means that a high true (active high) signal is high or that a low true (active low) signal is low			
"deasserted"	Means that a high tru is high	e (active high) signal	is low or that a low tru	e (active low) signal	
Examples:	Signal/Symbol	Logic State	Signal State	Voltage	
	PIN	True	Asserted	V _{IL} /V _{OL}	
	PIN	False	Deasserted	V_{IH}/V_{OH}	
	PIN	True	Asserted	V_{IH}/V_{OH}	
	PIN	False	Deasserted	V_{IL}/V_{OL}	

Note: Values for $V_{IL}, V_{OL}, V_{IH},$ and V_{OH} are defined by individual product specifications.

FEATURES

Digital Signal Processing Core

- Efficient, object code compatible with the 24-bit DSP56000 core family engine
- Up to 44 Million Instructions Per Second (MIPS)—22.7 ns instruction cycle at 88 MHz
- Highly parallel instruction set with unique DSP addressing modes
- Two 56-bit accumulators including extension byte
- Parallel 24 × 24-bit multiply-accumulate in 1 instruction cycle (2 clock cycles)
- Double precision 48×48 -bit multiply with 96-bit result in 6 instruction cycles
- 56-bit addition/subtraction in 1 instruction cycle
- Fractional and integer arithmetic with support for multiprecision arithmetic
- Hardware support for block floating-point Fast Fourier Transforms (FFT)
- Hardware nested DO loops
- Zero-overhead fast interrupts (2 instruction cycles)
- Four 24-bit internal data buses and three 16-bit internal address buses for simultaneous accesses to one program and two data memories
- Fabricated in high-density CMOS

Memory

- On-chip modified Harvard architecture, which permits simultaneous accesses to program and two data memories
- Bootstrap loading from Serial Host Interface or External Memory Interface

 Table 1
 Memory Configuration (Word width is 24 bits)

Mode	Program		X D	Data	Y I	Data	Bootstrap
PE	ROM	RAM	ROM	RAM	ROM	RAM	ROM
0	6400	None	512	1024	512	2176	52
1	5120	1024	512	1024	512	1152	52

Peripheral and Support Circuits

- Serial Audio Interface (SAI) includes two receivers and three transmitters, master or slave capability, implementation of I²S, Sony, and Matsushita audio protocols; and two sets of SAI interrupt vectors
- Serial Host Interface (SHI) features single master capability, 10-word receive FIFO, and support for 8-, 16-, and 24-bit words
- External Memory Interface (EMI), implemented as a peripheral supporting:
 - Page-mode DRAMs (one or two chips): 64 K \times 4, 256 K \times 4, and 4 M \times 4 bits
 - SRAMs (one to four): 256 K × 8 bits
 - Data bus may be 4 or 8 bits wide
 - Data words may be 8, 12, 16, 20, or 24 bits wide
- Four dedicated, independent, programmable General Purpose Input/Output (GPIO) lines
- On-chip peripheral registers memory mapped in data memory space
- Three external interrupt request pins
- On-Chip Emulation (OnCE) port for unobtrusive, processor speedindependent debugging
- Software-programmable, Phase Lock Loop-based (PLL) frequency synthesizer for the core clock
- Power-saving Wait and Stop modes
- Fully static, HCMOS design for operating frequencies down to DC
- 80-pin plastic Quad Flat Pack surface-mount package; $14 \times 14 \times 2.20$ mm (2.15–2.45 mm range); 0.65 mm lead pitch
- Complete pinout compatibility between DSP56009, DSP56004, DSP56004ROM, and DSP56007 for easy upgrades
- 5 V power supply

PRODUCT DOCUMENTATION

Table 2 lists the documents that provide a complete description of the DSP56007 and are required to design properly with the part. Documentation is available from a local Motorola distributor, a Motorola semiconductor sales office, a Motorola Literature Distribution Center, or through the Motorola DSP home page on the Internet (the source for the latest information).

Document Name	Description of Content	Order Number
DSP56000 Family Manual	DSP56000 core family architecture and the 24-bit core processor and instruction set	DSP56KFAMUM/AD
DSP56007 User's Manual	Memory, peripherals, and interfaces	DSP56007UM/AD
DSP56007 Technical Data	Electrical and timing specifications, and pin and package descriptions	DSP56007/D

Table 2	DSP56007 Documentation	
	DSI 50007 Documentation	

dsp

Product Documentation

SECTION 1

SIGNAL/CONNECTION DESCRIPTIONS

SIGNAL GROUPINGS

The DSP56007 input and output signals are organized into the nine functional groups, as shown in **Table 1-1**. The individual signals are illustrated in **Figure 1-1**.

Functional Group	Number of Signals	Detailed Description
Power (V _{CC})	9	Table 1-2
Ground (GND)	13	Table 1-3
Phase Lock Loop (PLL)	3	Table 1-4
External Memory Interface (EMI)	29	Table 1-5 andTable 1-6
Interrupt and Mode Control	4	Table 1-7
Serial Host Interface (SHI)	5	Table 1-8
Serial Audio Interface (SAI)	9	Table 1-9 andTable 1-10
General Purpose Input/Output (GPIO)	4	Table 1-11
On-Chip Emulation (OnCE) port	4	Table 1-12
Total	80	

Table 1-1 DSP56007 Functional Group Signal Allocations

Signal Groupings

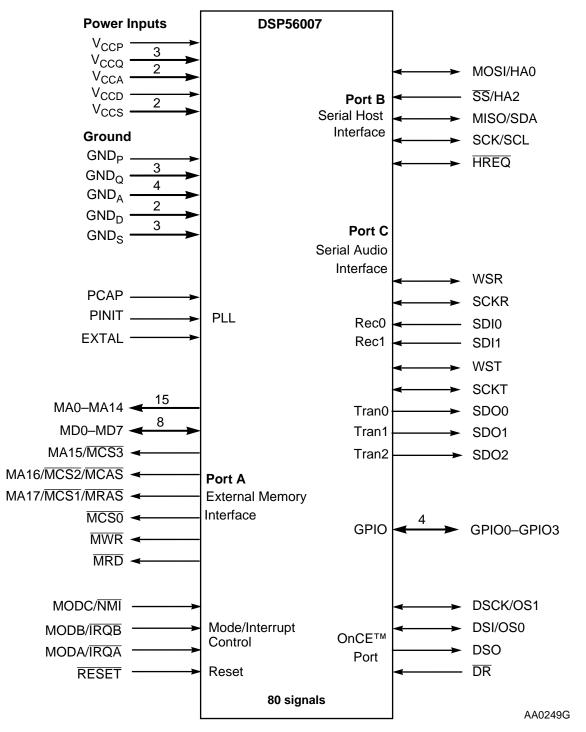


Figure 1-1 DSP56007 SIgnals

Power

POWER

Power Name	Description
V _{CCP}	PLL Power — V_{CCP} provides isolated power for the Phase Lock Loop (PLL). The voltage should be well-regulated and the input should be provided with an extremely low impedance path to the V_{CC} power rail.
V _{CCQ}	Quiet Power — V_{CCQ} provides isolated power for the internal processing logic. This input must be tied externally to all other chip power inputs. The user must provide adequate external decoupling capacitors.
V _{CCA}	$\begin{array}{c} \textbf{Address Bus Power} \\ -V_{CCA} \text{ provides isolated power for sections of the address bus} \\ I/O \text{ drivers. This input must be tied externally to all other chip power inputs. The} \\ user must provide adequate external decoupling capacitors. \end{array}$
V _{CCD}	Data Bus Power — V_{CCD} provides isolated power for sections of the data bus I/O drivers. This input must be tied externally to all other chip power inputs. The user must provide adequate external decoupling capacitors.
V _{CCS}	Serial Interface Power— V_{CCS} provides isolated power for the SHI and SAI. This input must be tied externally to all other chip power inputs. The user must provide adequate external decoupling capacitors.

Table 1-2Power Inputs

GROUND

Ground Name	Description
GND _P	PLL Ground —GND _P is ground dedicated for PLL use. The connection should be provided with an extremely low-impedance path to ground. V_{CCP} should be bypassed to GND _P by a 0.47 μ F capacitor located as close as possible to the chip package.
GND _Q	Quiet Ground — GND_Q provides isolated ground for the internal processing logic. This connection must be tied externally to all other chip ground connections. The user must provide adequate external decoupling capacitors.
GND _A	Address Bus Ground— GND_A provides isolated ground for sections of the address bus I/O drivers. This connection must be tied externally to all other chip ground connections. The user must provide adequate external decoupling capacitors.
GND _D	Data Bus Ground —GND _D provides isolated ground for sections of the data bus I/O drivers. This connection must be tied externally to all other chip ground connections. The user must provide adequate external decoupling capacitors.
GND _S	Serial Interface Ground —GND _S provides isolated ground for the SHI and SAI. This connection must be tied externally to all other chip ground connections. The user must provide adequate external decoupling capacitors.

 Table 1-3
 Grounds

CLOCK AND PLL SIGNALS

Note: While the PLL on this DSP is identical to the PLL described in the *DSP56000 Family Manual*, two of the signals have not been implemented externally. Specifically, there is no PLOCK signal or CKOUT signal available. Therefore, the internal clock is not directly accessible and there is no external indication that the PLL is locked. These signals were omitted to reduce the number of pins and allow this DSP to be put in a smaller, less expensive package.

Signal Name	Signal Type	State during Reset	Signal Description
EXTAL	Input	Input	External Clock/Crystal —This input should be connected to an external clock source. If the PLL is enabled, this signal is internally connected to the on-chip PLL. The PLL can multiply the frequency on the EXTAL pin to generate the internal DSP clock. The PLL output is divided by two to produce a four-phase instruction cycle clock, with the minimum instruction time being two PLL output clock periods. If the PLL is disabled, EXTAL is divided by two to produce the four-phase instruction cycle clock.
PCAP	Input	Input	PLL Filter Capacitor —This input is used to connect a high- quality (high "Q" factor) external capacitor needed for the PLL filter. The capacitor should be as close as possible to the DSP with heavy, short traces connecting one terminal of the capacitor to PCAP and the other terminal to V_{CCP} . The required capacitor value is specified in Table 2-6 on page 2-6.Note:When short lock time is critical, low dielectric absorption capacitors such as polystyrene, polypropylene, or teflon are recommended.
			If the PLL is not used (i.e., it remains disabled at all times), there is no need to connect a capacitor to the PCAP pin. It may remain unconnected, or be tied to either V_{cc} or GND.
PINIT	Input	Input	PLL Initialization (PINIT) —During the assertion of hardware reset, the value on the PINIT line is written into the PEN bit of the PCTL register. When set, the PEN bit enables the PLL by causing it to derive the internal clocks from the PLL voltage controlled oscillator output. When the bit is cleared, the PLL is disabled and the DSP's internal clocks are derived from the clock connected to the EXTAL signal. After hardware RESET is deasserted, the PINIT signal is ignored.

 Table 1-4
 Clock and PLL Signals

EXTERNAL MEMORY INTERFACE (EMI)

Signal Name	Signal Type	State during Reset	Signal Description
MA0-MA14	Output	Table 1-6	Memory Address Lines 0–14 —The MA0–MA10 lines provide the multiplexed row/column addresses for DRAM accesses. Lines MA0–MA14 provide the non-multiplexed address lines 0–14 for SRAM accesses.
MA15	Output	Table 1-6	Memory Address Line 15 (MA15) —This line functions as the non-multiplexed address line 15.
MCS3			Memory Chip Select 3 (MCS3) —For SRAM accesses, this line functions as memory chip select 3.
MA16	Output	Table 1-6	Memory Address Line 16 (MA16) —This line functions as the non-multiplexed address line 16 or as memory chip select 2 for SRAM accesses.
MCS2			Memory Chip Select 2 (MCS2) —For SRAM access, this line functions as memory chip select 2.
MCAS			Memory Column Address Strobe (MCAS) —This line functions as the Memory Column Address Strobe (MCAS) during DRAM accesses.
MA17	Output	Table 1-6	Memory Address Line 17 (MA17) —This line functions as the non-multiplexed address line 17.
MCS1			Memory Chip Select 1 (MCS1) —This line functions as chip select 1 for SRAM accesses.
MRAS			Memory Row Address Strobe (MRAS)—This line also functions as the Memory Row Address Strobe during DRAM accesses.
MCS0	Output	Table 1-6	Memory Chip Select 0 —This line functions as memory chip select 0 for SRAM accesses.
MWR	Output	Table 1-6	Memory Write Strobe —This line is asserted when writing to external memory.
MRD	Output	Table 1-6	Memory Read Strobe —This line is asserted when reading external memory.

External Memory Interface (EMI)

Signal Name	Signal Type	State during Reset	Signal Description
MD0-MD7	Bidi- rectional	Tri-stated	Data Bus —These signals provide the bidirectional data bus for EMI accesses. They are inputs during reads from external memory, outputs during writes to external memory, and tri- stated if no external access is taking place. If the data bus width is defined as four bits wide, only signals MD0–MD3 are active, while signals MD4–MD7 remain tri-stated. While tri-stated, MD0–MD7 are disconnected from the pins and do not require external pull-ups.

Table 1-5	External Memory	Interface (EMI)	Signals	(Continued)
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Table 1-6 EMI States during Reset and Stop States

Signal	Operating Mode					
Signal	Hardware Reset	Software Reset	Individual Reset	Stop Mode		
MA0-MA14	Driven High	Previous State	Previous State	Previous State		
MA15	Driven High	Driven High	Previous State	Previous State		
MCS3	Driven High	Driven High	Driven High	Driven High		
MA16	Driven High	Driven High	Previous State	Previous State		
MCS2	Driven High	Driven High	Driven High	Driven High		
MCAS: DRAM refresh disabled DRAM refresh enabled	Driven High Driven High	Driven High Driven High	Driven High Driven Low	Driven High Driven High		
MA17	Driven High	Driven High	Previous State	Previous State		
MCS1	Driven High	Driven High	Driven High	Driven High		
MRAS: DRAM refresh disabled DRAM refresh enabled	Driven High Driven High	Driven High Driven High	Driven High Driven Low	Driven High Driven High		
MCS0	Driven High	Driven High	Driven High	Driven High		
MWR	Driven High	Driven High	Driven High	Driven High		
MRD	Driven High	Driven High	Driven High	Driven High		

INTERRUPT AND MODE CONTROL

The interrupt and mode control signals select the DSP's operating mode as it comes out of hardware reset and receives interrupt requests from external sources after reset.

Signal Name	Signal Type	State during Reset	Signal Description
MODA	Input	Input (MODA)	Mode Select A—This input signal has three functions:
			 to work with the MODB and MODC signals to select the DSP's initial operating mode, to allow an external device to request a DSP interrupt after internal synchronization, and to turn on the internal clock generator when the DSP is in the Stop processing state, causing the DSP to resume processing.
			MODA is read and internally latched in the DSP when the processor exits the Reset state. The logic state present on the MODA, MODB, and MODC pins selects the initial DSP operating mode. Several clock cycles after leaving the Reset state, the MODA signal changes to the external interrupt request IRQA. The DSP operating mode can be changed by software after reset.
ĪRQĀ			External Interrupt Request A (IRQA)—The I RQA input is a synchronized external interrupt request. It may be programmed to be level-sensitive or negative-edge-triggered. When the signal is edge-triggered, triggering occurs at a voltage level and is not directly related to the fall time of the interrupt signal. However, as the fall time of the interrupt signal increases, the probability that noise on I RQA will generate multiple interrupts also increases.
			While the DSP is in the Stop mode, asserting \overline{IRQA} gates on the oscillator and, after a clock stabilization delay, enables clocks to the processor and peripherals. Hardware reset causes this input to function as MODA.

 Table 1-7
 Interrupt and Mode Control Signals

Interrupt and Mode Control

Signal Name	Signal Type	State during Reset	Signal Description	
MODB	Input	Input (MODB)	Mode Select B—This input signal has two functions:	
			 to work with the MODA and MODC signals to select the DSP's initial operating mode, and to allow an external device to request a DSP interrupt after internal synchronization. 	
			MODB is read and internally latched in the DSP when the processor exits the Reset state. The logic state present on the MODA, MODB, and MODC pins selects the initial DSP operating mode. Several clock cycles after leaving the Reset state, the MODB signal changes to the external interrupt request IRQB. The DSP operating mode can be changed by software after reset.	
ĪRQB			External Interrupt Request B (IRQB)—The IRQB input is synchronized external interrupt request. It may be programmed to be level-sensitive or negative-edge- triggered. When the signal is edge-triggered, triggering occurs at a voltage level and is not directly related to the time of the interrupt signal. However, as the fall time of t interrupt signal increases, the probability that noise on IR will generate multiple interrupts also increases. Hardwar reset causes this input to function as MODB.	

Table 1-7 Interrupt and Mode Control Signals (Continued)

Interrupt and Mode Control

Signal Name	Signal Type	State during Reset	Signal Description
MODC	Input, edge- triggered	Input (MODC)	 Mode Select C—This input signal has two functions: to work with the MODA and MODB signals to select the DSP's initial operating mode, and to allow an external device to request a DSP interrupt after internal synchronization.
			MODC is read and internally latched in the DSP when the processor exits the Reset state. The logic state present on the MODA, MODB, and MODC pins selects the initial DSP operating mode. Several clock cycles after leaving the Reset state, the MODC signal changes to the Non-Maskable Interrupt request, NMI. The DSP operating mode can be changed by software after reset.
NMI			Non-Maskable Interrupt Request —The NMI input is a negative-edge-triggered external interrupt request. This is a level 3 interrupt that can not be masked out. Triggering occurs at a voltage level and is not directly related to the fall time of the interrupt signal. However, as the fall time of the interrupt signal increases, the probability that noise on NMI will generate multiple interrupts also increases. Hardware reset causes this input to function as MODC.
RESET	input	active	RESET —This input causes a direct hardware reset of the processor. When RESET is asserted, the DSP is initialized and placed in the Reset state. A Schmitt-trigger input is used for noise immunity. When the reset signal is deasserted, the initial DSP operating mode is latched from the MODA, MODB, and MODC signals. The DSP also samples the PINIT signal and writes its status into the PEN bit of the PLL Control Register. When the DSP comes out of the Reset state, deassertion occurs at a voltage level and is not directly related to the rise time of the RESET signal. However, the probability that noise on RESET will generate multiple resets increases with increasing rise time of the RESET signal.
			For proper hardware reset to occur, the clock must be active, since a number of clock ticks are required for proper propagation of the hardware Reset state.

 Table 1-7
 Interrupt and Mode Control Signals (Continued)

Serial Host Interface (SHI)

SERIAL HOST INTERFACE (SHI)

The Serial Host Interface (SHI) has five I/O signals, which may be configured to operate in either SPI or I^2C mode. **Table 1-8** lists the SHI signals.

Signal Name	Signal Type	State during Reset	Signal Description
SCK	Input or Output	Tri-stated	SPI Serial Clock (SCK) —The SCK signal is an output when the SPI is configured as a master, and a Schmitt- trigger input when the SPI is configured as a slave. When the SPI is configured as a master, the SCK signal is derived from the internal SHI clock generator. When the SPI is configured as a slave, the SCK signal is an input, and the clock signal from the external master synchronizes the data transfer. The SCK signal is ignored by the SPI if it is defined as a slave and the Slave Select (SS) signal is not asserted. In both the master and slave SPI devices, data is shifted on one edge of the SCK signal and is sampled on the opposite edge where data is stable. Edge polarity is determined by the SPI transfer protocol.
SCL	Input or Output		I²C Serial Clock (SCL) —SCL carries the clock for bus transactions in the I ² C mode. SCL is a Schmitt-trigger input when configured as a slave, and an open-drain output when configured as a master. SCL should be connected to V_{CC} through a pull-up resistor. The maximum allowed internally generated bit clock frequency is $^{Fosc}/_4$ for the SPI mode and $^{Fosc}/_6$ for the I ² C mode where F_{osc} is the clock on EXTAL. The maximum allowed externally generated bit clock frequency is $^{Fosc}/_3$ for the SPI mode and $^{Fosc}/_5$ for the I ² C mode. This signal is tri-stated during hardware reset, software reset, or individual reset (no need for external pull-up in this state).

 Table 1-8
 Serial Host Interface (SHI) signals

Serial Host Interface (SHI)

Signal Name	Signal Type	State during Reset	Signal Description
MISO	Input or Output	Tri-stated	SPI Master-In-Slave-Out (MISO) —When the SPI is configured as a master, MISO is the master data input line. The MISO signal is used in conjunction with the MOSI signal for transmitting and receiving serial data. This signal is a Schmitt-trigger input when configured for the SPI Master mode, an output when configured for the SPI Slave mode, and tri-stated if configured for the SPI Slave mode when \overline{SS} is deasserted.
SDA	Input or Output		I ² C Serial Data and Acknowledge (SDA) —In I ² C mode, SDA is a Schmitt-trigger input when receiving and an open-drain output when transmitting. SDA should be connected to V_{CC} through a pull-up resistor. SDA carries the data for I ² C transactions. The data in SDA must be stable during the high period of SCL. The data in SDA is only allowed to change when SCL is low. When the bus is free, SDA is high. The SDA line is only allowed to change during the time SCL is high in the case of Start and Stop events. A high-to-low transition of the SDA line while SCL is high is an unique situation, and is defined as the Start event. A low-to-high transition of SDA while SCL is high is an unique situation, and is defined as the Stop event.
MOSI	Input or	Tri-stated	reset, or individual reset (no need for external pull-up in this state). SPI Master-Out-Slave-In (MOSI)—When the SPI is
	Output		configured as a master, MOSI is the master data output line. The MOSI signal is used in conjunction with the MISO signal for transmitting and receiving serial data. MOSI is the slave data input line when the SPI is configured as a slave. This signal is a Schmitt-trigger input when configured for the SPI Slave mode.
HA0	Input		I²C Slave Address 0 (HA0) —This signal uses a Schmitt- trigger input when configured for the I ² C mode. When configured for I ² C Slave mode, the HA0 signal is used to form the slave device address. HA0 is ignored when the SHI is configured for the I ² C Master mode.
			Note: This signal is tri-stated during hardware reset, software reset, or individual reset (no need for external pull-up in this state).

 Table 1-8
 Serial Host Interface (SHI) signals (Continued)

Serial Host Interface (SHI)

Signal Name	Signal Type	State during Reset	Signal Description
SS	Input	Tri-stated	SPI Slave Select (SS)—This signal is an active low Schmitt-trigger input when configured for the SPI mode. When configured for the SPI Slave mode, this signal is used to enable the SPI slave for transfer. When configured for the SPI Master mode, this signal should be kept deasserted. If it is asserted while configured as SPI master, a bus error condition will be flagged.
HA2	Input		I^2C Slave Address 2 (HA2)—This signal uses a Schmitt-trigger input when configured for the I^2C mode. When configured for the I^2C Slave mode, the HA2 signal is used to form the slave device address. HA2 is ignored in the I^2C Master mode. If \overline{SS} is deasserted, the SHI ignores SCK clocks and keeps the MISO output signal in the high-impedance state.Note:This signal is tri-stated during hardware reset, software reset, or individual reset (no need for
HREQ	Input or Output	Tri-stated	 Host Request—This signal is an active low Schmitt-trigger input when configured for the Master mode, but an active low output when configured for the Slave mode. When configured for the Slave mode, HREQ is asserted to indicate that the SHI is ready for the next data word transfer and deasserted at the first clock pulse of the new data word transfer. When configured for the Master mode, HREQ is an input and when asserted by the external slave device, it will trigger the start of the data word transfer by the master. After finishing the data word transfer, the master will await the next assertion of HREQ to proceed to the next transfer.
			Note: This signal is tri-stated during hardware, software, individual reset, or when the HREQ[1:0] bits (in the HCSR) are cleared (no need for external pull-up in this state).

Table 1-8 Serial Host Interface (SHI) signals (Continued)

Serial Audio Interface (SAI)

SERIAL AUDIO INTERFACE (SAI)

The SAI is composed of separate receiver and transmitter sections.

SAI Receiver Section

Signal Type	State during Reset	Signal Description
Input	Tri-stated	 Serial Data Input 0—While in the high impedance state, the internal input buffer is disconnected from the pin and no external pull-up is necessary. SDI0 is the serial data input for receiver 0. Note: This signal is high impedance during hardware or software reset, while receiver 0 is disabled (R0EN = 0), or while the DSP is in the Stop state.
Input	Tri-stated	 Serial Data Input 1—While in the high impedance state, the internal input buffer is disconnected from the pin and no external pull-up is necessary. SDI1 is the serial data input for receiver 1. Note: This signal is high impedance during hardware or software reset, while receiver 1 is disabled (R1EN = 0), or while the DSP is in the Stop state.
Input or Output	Tri-stated	 Receive Serial Clock—SCKR is an output if the receiver section is programmed as a master, and a Schmitt-trigger input if programmed as a slave. While in the high impedance state, the internal input buffer is disconnected from the pin and no external pull-up is necessary. Note: SCKR is high impedance if all receivers are disabled (individual reset) and during hardware or software reset, or while the DSP is in the Stop state.
	Type Input Input Input	Type Reset Input Tri-stated Input Tri-stated Input Tri-stated Input or Tri-stated

Table 1-9 Serial Audio Interface (SAI) Receiver signals

Serial Audio Interface (SAI)

Signal Name	Signal Type	State during Reset	Signal Description
WSR	Input or Output	Tri-stated	Word Select Receive (WSR) —WSR is an output if the receiver section is configured as a master, and a Schmitt-trigger input if configured as a slave. WSR is used to synchronize the data word and to select the left/right portion of the data sample.
			Note: WSR is high impedance if all receivers are disabled (individual reset), during hardware reset, during software reset, or while the DSP is in the Stop state. While in the high impedance state, the internal input buffer is disconnected from the signal and no external pull-up is necessary.

Table 1-9 Serial Audio Interface (SAI) Receiver signals (Continued)

SAI Transmitter Section

Signal Name	Signal Type	State during Reset	Signal Description
SDO0	Output	Driven High	Serial Data Output 0 (SDO0) —SDO0 is the serial output for transmitter 0. SDO0 is driven high if transmitter 0 is disabled, during individual reset, hardware reset, and software reset, or when the DSP is in the Stop state.
SDO1	Output	Driven High	Serial Data Output 1 (SDO1) —SDO1 is the serial output for transmitter 1. SDO1 is driven high if transmitter 1 is disabled, during individual reset, hardware reset and software reset, or when the DSP is in the Stop state.
SDO2	Output	Driven High	Serial Data Output 2 (SDO2) —SDO2 is the serial output for transmitter 2. SDO2 is driven high if transmitter 2 is disabled, during individual reset, hardware reset and software reset, or when the DSP is in the Stop state.
SCKT	Input or Output	Tri-stated	Serial Clock Transmit (SCKT)—This signal provides the clock for the SAI. SCKT can be an output if the transmit section is configured as a master, or a Schmitt-trigger input if the transmit section is configured as a slave. When the SCKT is an output, it provides an internally generated SAI transmit clock to external circuitry. When the SCKT is an input, it allows external circuitry to clock data out of the SAI.
			Note: SCKT is high impedance if all transmitters are disabled (individual reset), during hardware reset, software reset, or while the DSP is in the Stop state. While in the high impedance state, the internal input buffer is disconnected from the pin and no external pull-up is necessary.
WST	Input or Output	Tri-stated	Word Select Transmit (WST) —WST is an output if the transmit section is programmed as a master, and a Schmitt-trigger input if it is programmed as a slave. WST is used to synchronize the data word and select the left/right portion of the data sample.
			Note: WST is high impedance if all transmitters are disabled (individual reset), during hardware or software reset, or while the DSP is in the Stop state. While in the high impedance state, the internal input buffer is disconnected from the pin and no external pull-up is necessary.

Table 1-10	Serial Audio Interface (SAI) Transmitter signals
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General Purpose I/O

GENERAL PURPOSE I/O

Signal	Signal	State during	Signal Description
Name	Type	Reset	
GPIO0- GPIO3	Standard Output, Open-drain Output, or Input	Disconnected	 GPIO lines can be used for control and handshake functions between the DSP and external circuitry. Each GPIO line can be configured individually as disconnected, open-drain output, standard output, or an input. Note: Hardware reset or software reset configures all the GPIO lines as disconnected (external circuitry connected to these pins may need pull-ups until the pins are configured for operation).

 Table 1-11
 General Purpose I/O (GPIO) Signals

ON-CHIP EMULATION (OnCE™) PORT

There are four signals associated with the OnCE port controller and its serial interface.

Signal Name	Signal Type	State during Reset	Signal Description
DSI	Input	Output, Driven Low	Debug Serial Input (DSI) —The DSI signal is the signal through which serial data or commands are provided to the OnCE port controller. The data received on the DSI signal will be recognized only when the DSP has entered the Debug mode of operation. Data must have valid TTL logic levels before the serial clock falling edge. Data is always shifted into the OnCE port Most Significant Bit (MSB) first.
OS0	Output		Operating Status 0 (OS0) —When the DSP is not in the Debug mode, the OS0 signal provides information about the DSP status if it is an output and used in conjunction with the OS1 signal. When switching from output to input, the signal is tri-stated.
			Note: If the OnCE port is in use, an external pull-down resistor should be attached to the DSI/OS0 signal. If the OnCE port is not in use, the resistor is not required.

 Table 1-12
 On-Chip Emulation Port Signals

DSCK		Reset	Signal Description
	Input	Output, Driven Low	Debug Serial Clock (DSCK) —The DSCK/OS1 signal, when an input, is the signal through which the serial clock is supplied to the OnCE port. The serial clock provides pulses required to shift data into and out of the OnCE port. Data is clocked into the OnCE port on the falling edge and is clocked out of the OnCE port on the rising edge.
OS1	Output		 Operating Status 1 (OS1)—If the OS1 signal is an output and used in conjunction with the OS0 signal, it provides information about the DSP status when the DSP is not in the Debug mode. The debug serial clock frequency must be no greater than 1/8 of the processor clock frequency. The signal is tri-stated when it is changing from input to output. Note: If the OnCE port is in use, an external pull-down resistor should be attached to the DSCK/OS1 pin. If the OnCE port is not in use, the resistor is not required.
DSO	Output	Driven High	Debug Serial Output (DSO)—The DSO line provides the data contained in one of the OnCE port controller registers as specified by the last command received from the command controller. The Most Significant Bit (MSB) of the data word is always shifted out of the OnCE port first. Data is clocked out of the OnCE port on the rising edge of DSCK. The DSO line also provides acknowledge pulses to the external command controller. When the DSP enters the Debug mode, the DSO line will be pulsed low to indicate that the OnCE port is waiting for commands. After receiving a read command, the DSO line will be pulsed low to indicate that the requested data is available and the OnCE port is ready to receive clock pulses in order to deliver the data. After receiving a write command, the DSO line will be pulsed low to indicate that the OnCE port is ready to receive the data to be written; after the data is written, another acknowledge pulse will be provided. Note: During hardware reset and when idle, the DSO line is held high.

 Table 1-12
 On-Chip Emulation Port Signals (Continued)

On-Chip Emulation (OnCETM) Port

Signal	Signal	State during	Signal Description
Name	Type	Reset	
DR	Input	Input	Debug Request (\overline{DR}) —The debug request input provides a means of entering the Debug mode of operation. This signal, when asserted (pulled low), will cause the DSP to finish the current instruction being executed, to save the instruction pipeline information, to enter the Debug mode, and to wait for commands to be entered from the debug serial input line. While the DSP is in the Debug mode, the user can reset the OnCE port controller by asserting \overline{DR} , waiting for an acknowledge pulse on DSO, and then deasserting \overline{DR} . It may be necessary to reset the OnCE port controller in cases where synchronization between the OnCE port controller and external circuitry is lost. Asserting \overline{DR} when the DSP is in the Wait or the Stop mode, and keeping it asserted until an acknowledge pulse in the DSP is produced, puts the DSP into the Debug mode. After receiving the acknowledge pulse, \overline{DR} must be deasserted before sending the first OnCE port command. For more information, see Methods Of Entering The Debug Mode in the DSP56000 Family Manual.Note:If the OnCE port is not in use, an external pull-up resistor should be attached to the \overline{DR} line.

Table 1-12 On-Chip Emulation Port Signals (Continued)

dsp

SECTION 2

SPECIFICATIONS

INTRODUCTION

The DSP56007 is fabricated in high density CMOS with Transistor-Transistor Logic (TTL) compatible inputs and outputs.

MAXIMUM RATINGS

CAUTION

This device contains circuitry protecting against damage due to high static voltage or electrical fields; however, normal precautions should be taken to avoid exceeding maximum voltage ratings. Reliability is enhanced if unused inputs are tied to an appropriate logic voltage level (e.g., either GND or V_{CC}).

Note: In the calculation of timing requirements, adding a maximum value of one specification to a minimum value of another specification does not yield a reasonable sum. A maximum specification is calculated using a worst case variation of process parameter values in one direction. The minimum specification is calculated using the worst case for the same parameters in the opposite direction. Therefore, a "maximum" value for a specification will never occur in the same device that has a "minimum" value for another specification; adding a maximum to a minimum represents a condition that can never exist.

Thermal characteristics

Rating	Symbol	Value	Unit
Supply Voltage	V _{CC}	-0.3 to +7.0	V
All Input Voltages	V _{IN}	(GND – 0.25) to (V _{CC} + 0.25)	V
Current Drain per Pin excluding $V_{\mbox{\scriptsize CC}}$ and GND	Ι	10	mA
Operating Temperature Range: • 50 and 66 MHz • 88 MHz	TJ	-40 to +125 -40 to +110	°C °C
Storage Temperature	T _{STG}	-55 to +125	°C

Table 2-1 Maximum Ratings (GND = $0 V_{dc}$)

THERMAL CHARACTERISTICS

Table 2-2 Ther	mal Characteristics
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Characteristic	Symbol	QFP Value ³	QFP Value ⁴	Unit
Junction-to-ambient thermal resistance ¹	$R_{\theta JA}$ or θ_{JA}	61.5	37	°C/W
Junction-to-case thermal resistance ²	$R_{\theta JC}$ or θ_{JC}	11.8		°C/W
Thermal characterization parameter	Ψ_{JT}	2.7	_	°C/W
Notor 1 Innotion to ambient thermal resis			1	1 . 1 1

Notes: 1. Junction-to-ambient thermal resistance is based on measurements on a horizontal-single-sided Printed Circuit Board per SEMI G38-87 in natural convection.(SEMI is Semiconductor Equipment and Materials International, 805 East Middlefield Rd., Mountain View, CA 94043, (415) 964-5111)

 Junction-to-case thermal resistance is based on measurements using a cold plate per SEMI G30-88, with the exception that the cold plate temperature is used for the case temperature.

3. These are measured values. See note 1 for test board conditions.

4. These are measured values; testing is not complete. Values were measured on a non-standard four-layer thermal test board (two internal planes) at one watt in a horizontal configuration.

DC ELECTRICAL CHARACTERISTICS

Characteristics	Symbol	50 MHz			66 MHz			88 MHz			Unit
Characteristics	Symbol	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
Supply voltage	V _{CC}	4.75	5.0	5.25	4.75	5.0	5.25	4.75	5.0	5.25	V
Input high voltage • EXTAL • RESET • MODA, MODB, MODC	V _{IHC} V _{IHR} V _{IHM}	4.0 2.5 3.5		V _{CC} V _{CC} V _{CC}	4.0 2.5 3.5	_ _ _	V _{CC} V _{CC} V _{CC}	4.0 2.5 3.5	 	V _{CC} V _{CC} V _{CC}	V V V
• SHI inputs ¹	V _{IHS}	$0.7 \times V_{CC}$	_	V _{CC}	$0.7 \times V_{CC}$	-	V _{CC}	$egin{array}{c} 0.7 \times V_{CC} \end{array}$	_	V _{CC}	V
All other inputs	V _{IH}	2.0	-	V _{CC}	2.0	-	V_{CC}	2.0	-	V_{CC}	V
Input low voltage EXTAL MODA, MODB, MODC SHI inputs¹ 	V _{ILC} V _{ILM} V _{ILS}	-0.5 -0.5 -0.5	_	0.4 2.0 0.3×	-0.5 -0.5 -0.5	_	0.4 2.0 0.3 ×	-0.5 -0.5 -0.5	_	0.4 2.0 0.3×	V V V
All other inputs	V _{IL}	-0.5	_	V _{CC} 0.8	-0.5	_	V _{CC} 0.8	-0.5	_	V _{CC} 0.8	v
Input leakage current • EXTAL, RESET, MODA, MODB, MODC, DR • Other Input Pins (@ 2.4 V/0.4 V)	I _{IN}	-1 -10	_	1 10	-1 -10	_	1 10	-1 -10	_	1 10	μA μA
High impedance (off-state) input current (@ 2.4 V / 0.4 V)	I _{TSI}	-10	—	10	-10	—	10	-10	—	10	μA
Output high voltage $(I_{OH} = -0.4 \text{ mA})$	V _{OH}	2.4	-		2.4	—		2.4	—	—	V
	V _{OL}			0.4	_	_	0.4		-	0.4	V
Internal Supply Current Normal mode Wait mode Stop mode² 	$I_{CCI} \\ I_{CCW} \\ I_{CCS}$		80 14 5	105 ⁴ 25 110		110 18 5	130 ⁴ 30 110		147 24 5	169 ⁴ 33 110	mA mA μA

 Table 2-3
 DC Electrical Characteristics

AC Electrical Characteristics

	50 MHz			66 MHz			88 MHz			Unit
	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	
		0.7	1.1	_	1.0	1.5		1.3	2.2	mA
IN		10			10			10		pF
	ŹIN		- 0.7 - 10	- 0.7 1.1	- 0.7 1.1 - $\Gamma_{\rm IN}$ - 10 - -	$\begin{array}{c c c c c c c c c c c c c c c c c c c $	$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	$\begin{array}{c ccccccccccccccccccccccccccccccccccc$

 Table 2-3
 DC Electrical Characteristics (Continued)

MOSI/HA0, SS/HA2, MISO/SDA, SCK/

2. In order to obtain these results, all inputs must be terminated (i.e., not allowed to float). PLL signals are disabled during Stop state.

3. Periodically sampled and not 100% tested

4. Maximum values are derived using the methodology described in **Section 4**. Actual maximums are application dependent and may vary widely from these numbers.

AC ELECTRICAL CHARACTERISTICS

The timing waveforms in the AC Electrical Characteristics are tested with a V_{II} maximum of 0.5 V and a V_{IH} minimum of 2.4 V for all pins, except EXTAL, RESET, MODA, MODB, MODC, and SHI pins (MOSI/HA0, SS/HA2, MISO/SDA, SCK/ SCL, HREQ). These pins are tested using the input levels set forth in the DC Electrical Characteristics. AC timing specifications that are referenced to a device input signal are measured in production with respect to the 50% point of the respective input signal's transition. DSP56007 output levels are measured with the production test machine V_{OL} and V_{OH} reference levels set at 0.8 V and 2.0 V, respectively.

All output delays are given for a 50 pF load unless otherwise specified. For load capacitance greater than 50 pF, the drive capability of the output pins typically decreases linearly:

- 1. At 1.5 ns per 10 pF of additional capacitance at all output pins except MOSI/HA0, MISO/SDA, SCK/SCL, HREQ
- 2. At 1.0 ns per 10 pF of additional capacitance at output pins MOSI/HA0, MISO/SDA, SCK/SCL, HREQ (in SPI mode only)

INTERNAL CLOCKS

For each occurrence of T_H , T_L , T_C , or I_{CYC} , substitute with the numbers in **Table 2-4**.

Characteristics	Symbol	Expression
Internal Operation Frequency	f	—
 Internal Clock High Period with PLL disabled with PLL enabled and MF ≤ 4 with PLL enabled and MF > 4 	T _H	$\begin{array}{c} & ET_{H} \\ (Min) & 0.48 \times T_{C} \\ (Max) & 0.52 \times T_{C} \\ (Min) & 0.467 \times T_{C} \\ (Max) & 0.533 \times T_{C} \end{array}$
 Internal Clock Low Period with PLL disabled with PLL enabled and MF ≤ 4 with PLL enabled and MF > 4 	TL	$\begin{array}{c} {\rm ET}_{\rm L} \\ ({\rm Min}) & 0.48 \times {\rm T}_{\rm C} \\ ({\rm Max}) & 0.52 \times {\rm T}_{\rm C} \\ ({\rm Min}) & 0.467 \times {\rm T}_{\rm C} \\ ({\rm Max}) & 0.533 \times {\rm T}_{\rm C} \end{array}$
Internal Clock Cycle Time	T _C	(DF /MF) × ET _C
Instruction Cycle Time	I _{CYC}	$2 \times T_{C}$

Table 2-4	Internal Clocks
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EXTERNAL CLOCK (EXTAL PIN)

The DSP56007 system clock is externally supplied via the EXTAL pin. Timings shown in this document are valid for clock rise and fall times of 3 ns maximum.

No.	Characteristics	Sym.	50	MHz	66 MHz		88	Unit	
110.	Characteristics		Min	Max	Min	Max	Min	Max	Unit
—	Frequency of External Clock (EXTAL Pin)	Ef	0	50	0	66	0	88	MHz
1	External Clock Input High—EXTAL Pin ¹ • with PLL disabled (46.7%–53.3% duty cycle) • with PLL enabled (42.5%–57.5% duty cycle)	ET _H	9.3 8.5	∞ 235500	7.1 6.4	∞ 235500	5.3 4.8	∞ 235500	ns ns

Table 2-5	External Clock	(EXTAL Pin)
	Linconnui Oloon	

Phase Lock Loop (PLL) Characteristics

No.	Characteristics	Com	50 MHz		66 MHz		88	Unit	
110.	Characteristics	Sym.	Min	Max	Min	Max	Min	Max	Unit
2	External Clock Input Low—EXTAL Pin ¹ • with PLL disabled (46.7%–53.3% duty cycle)	ETL	9.3	8	7.1	8	5.4	8	ns
	• with PLL enabled (42.5%–57.5% duty cycle)		8.5	235500	6.4	235500	4.8	235500	ns
3	External Clock Cycle Time ¹	ET _C							
	 with PLL disabled 		20	∞	15.15	∞	11.4	∞	ns
	 with PLL enabled 		20	409600	15.15	409600	11.4	409600	ns
4	Instruction Cycle Time = $I_{cyc} = 2 \times T_C^{1}$	I _{cyc}							
	• with PLL disabled		40	∞	30.3	∞	22.7	∞	ns
	 with PLL enabled 		40	819200	30.3	819200	22.7	819200	ns

 Table 2-5
 External Clock (EXTAL Pin) (Continued)

Note: 1. External Clock Input High and External Clock Input Low are measured at 50% of the input transition.

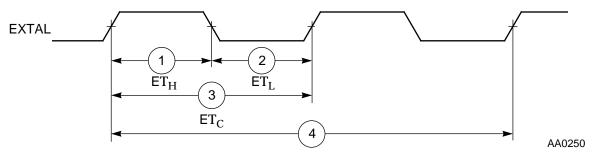


Figure 2-1 External Clock Timing

PHASE LOCK LOOP (PLL) CHARACTERISTICS

Table 2-6	Phase Lock	Loop (PLL)	Characteristics
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Characteristics	Expression	Min	Max	Unit						
VCO frequency when PLL enabled	MF×Ef	10	f^1	MHz						
PLL external capacitor (PCAP pin to V_{CCP})	$\begin{array}{c} MF \times C_{PCAP}{}^{1} \\ @ MF \leq 4 \\ @ MF > 4 \end{array}$	MF × 340 MF × 380	MF × 480 MF × 970	pF pF						
Note:1.Cpcap is the value of the PLL capacitor (connected between PCAP pin and V_{CCP}) for MF = 1.The recommended value for Cpcap is 400 pF for MF \leq 4 and 540 pF for MF > 4.The maximum VCO frequency is limited to the internal operation frequency, defined in Table 2-4.										

RESET, STOP, MODE SELECT, AND INTERRUPT TIMING

No.	Characteristics	Min	Max	Unit
10	Minimum RESET assertion width: PLL disabled PLL enabled¹ 	$25 imes T_{C}$ $2500 imes ET_{C}$		ns ns
14	Mode Select Setup Time	21	_	ns
15	Mode Select Hold Time	0		ns
16	Minimum Edge-triggered Interrupt Request Assertion Width	13		ns
16a	Minimum Edge-triggered Interrupt Request Deassertation Width	13		ns
18	Delay from IRQA, IRQB, NMI Assertion to GPIO Valid Caused by First Interrupt Instruction Execution	$12 \times T_{C} + T_{H}$		ns
22	Delay from General Purpose Output Valid to Interrupt Request Deassertation for Level Sensitive Fast Interrupts—If Second Interrupt Instruction is: ²			
	Single CycleTwo Cycles		$\begin{vmatrix} T_{\rm L} - 31 \\ (2 \times T_{\rm C}) + T_{\rm L} - 31 \end{vmatrix}$	ns
25	Duration of IRQA Assertion for Recovery from Stop State	12	$(2 \times 1_{\rm C}) + 1_{\rm L} - 31$	ns
		12		ns
27	 Duration for Level Sensitive IRQA Assertion to ensure interrupt service (when exiting "STOP") Stable External Clock, OMR Bit 6 = 1 Stable External Clock, PCTL Bit 17 = 1 	$\begin{array}{c} 6 \times T_{\rm C} + T_{\rm L} \\ 12 \end{array}$	—	ns ns
Note:	 This timing requirement is sensitive to the quality of the epin. For capacitor values <i>less than or equal to</i> 2 nF, asserting will ensure proper processor initialization for capacitors of for ceramic capacitors.) For capacitor values <i>greater than</i> 2 requirement will ensure proper processor initialization for (This is typical for Teflon, polystyrene, and polypropylene <i>greater than</i> 2 nF with a deltaC/C <i>greater than</i> 0.01% may r proper initialization. When using fast interrupts and IRQA and IRQB are define prevent multiple interrupt service. To avoid these timing mode is recommended when using fast interrupts. Long i Level-sensitive mode. 	g RESET accordin with a deltaC/C <i>l</i> nF, asserting RE or capacitors with e capacitors.) How require longer RE ed as level-sensiti restrictions, the N	ng to this timing requ less than 0.5%. (This is SET according to this a deltaC/C <i>less than</i> vever, capacitors with SET assertion to ensu ive, then timing 22 ap Negative Edge-trigge	irement s typical s timing 0.01%. n values ure oplies to red

Table 2-7Re	eset, Stop, Mode Select, and Interrup	ot Timing ($C_L = 50$	pF + 2 TTL Load	.s)	

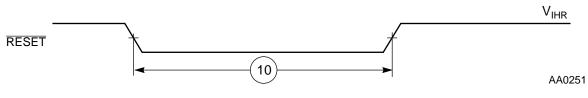


Figure 2-2 Reset Timing

RESET, Stop, Mode Select, and Interrupt Timing

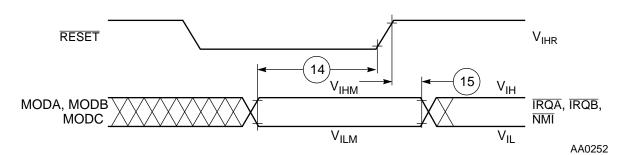
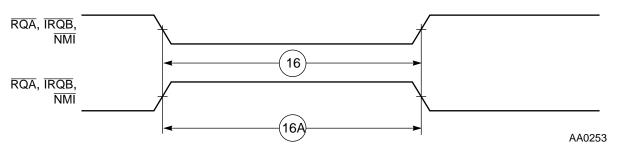


Figure 2-3 Operating Mode Select Timing





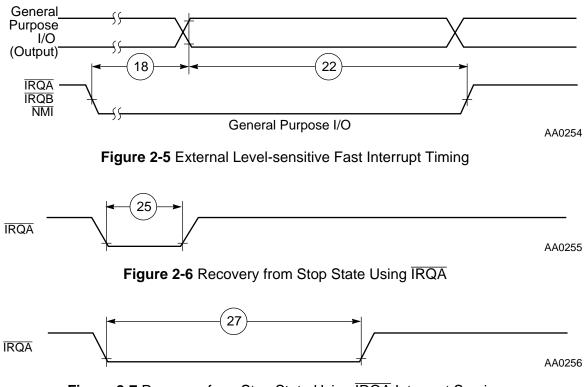


Figure 2-7 Recovery from Stop State Using IRQA Interrupt Service

EXTERNAL MEMORY INTERFACE (EMI) DRAM TIMING

 $(C_L = 50 \text{ pF} + 2 \text{ TTL Loads})$

			50 MHz		66 MHz 88 M			/ 11			
No.	Characteristics	Symbol	Timing	Expression	50 N	/IHZ	66 N	/IHZ	88 MHz		Unit
		5	Mode	•	Min	Max	Min	Max	Min	Max	
41	Page Mode Cycle Time	t _{PC}	slow fast	$\begin{array}{c} 4\times T_{C} \\ 3\times T_{C} \end{array}$	80 60	_	61 46	_	45.5 34.1	_	ns ns
42	RAS or RD Assertion to Data Valid	t _{RAC} , t _{GA}	slow fast	$\begin{array}{c} 7\times T_C - 16 \\ 5\times T_C - 16 \end{array}$	_	124 84		90 60	_	63.5 40.8	ns ns
43	CAS Assertion to Data Valid	T _{CAC}	slow fast	$\begin{array}{c} 3 \times \mathrm{T_{C}} - 10 \\ 2 \times \mathrm{T_{C}} - 10 \end{array}$	_	50 30	_	35 20		24.1 12.7	ns ns
44	Column Address Valid to Data Valid	t _{AA}	slow fast	$\begin{array}{c} 3\times T_{\rm C}+T_{\rm L}-7\\ 2\times T_{\rm C}+T_{\rm L}-7\\ 7\end{array}$		63 43	_	46 30	_	32.8 21.4	ns ns
45	CAS Assertion to Data Active	T _{CLZ}		0	0		0		0	_	ns
46	RAS Assertion Pulse Width ¹ (Page Mode Access Only)	t _{RASP}	slow fast	$\begin{array}{c} 3 \times T_{C} - 11 \\ + n \times 4 \times T_{C} \\ 2 \times T_{C} - 11 \\ + n \times 3 \times T_{C} \end{array}$	209 149	_	156 110	_	114 79.9	_	ns ns
47	RAS Assertion Pulse Width (Single Access Only)	t _{RAS}	slow fast	$7 \times T_{\rm C} - 11$ $5 \times T_{\rm C} - 11$	129 89		95 65		68.5 45.8		ns ns
48	RAS or CAS Deassertation to RAS Assertion	t _{RP} , T _{CRP}	slow fast	$\begin{array}{c} 5\times T_{C}-5\\ 3\times T_{C}-5\end{array}$	95 55		70 40	_	51.8 29.1	_	ns ns
49	CAS Assertion Pulse Width	T _{CAS}	slow fast	$\begin{array}{c} 3\times T_{C}-10\\ 2\times T_{C}-10 \end{array}$	50 30	_	35 20	_	24.1 12.7	_	ns ns
50	Last CAS Assertion to RAS Deassertation (Page Mode Access Only)	t _{RSH}	slow fast	$\begin{array}{c} 3 \times T_{C} - 15 \\ 2 \times T_{C} - 15 \end{array}$	45 25		30 15	_	19.1 7.7		ns ns
51	\overline{RAS} or \overline{WR} Assertion to \overline{CAS} Deassertation	T _{CSH} , T _{CWL}	slow fast	$\begin{array}{c} 7 \times T_{C} - 15 \\ 5 \times T_{C} - 15 \end{array}$	125 85		91 61		64.5 41.8	_	ns ns
52	RAS Assertion to CAS Assertion	t _{RCD}	slow fast	$\begin{array}{c} 4\times T_C - 13 \\ 3\times T_C - 13 \end{array}$	67 47		47 32		32.5 21.1	_	ns ns
53	RAS Assertion to Column Address Valid	t _{RAD}	slow fast	$\begin{array}{c} 3\times T_{C}+T_{H}-\\ 13\\ 2\times T_{C}+T_{H}-\\ 13 \end{array}$	57 37	_	40 25	_	26.8 15.4	_	ns ns

Table 2-8 External Memory Interface (EMI) DRAM Timing

External Memory Interface (EMI) DRAM Timing

Na	Characteristics	Symphol	Timing	Europation	50 N	ИНz	66 N	ИНz	88 MHz		Unit
No.	Characteristics	Symbol	Mode	Expression	Min	Max	Min	Max	Min	Max	ome
54	CAS Deassertation Pulse Width (Page Mode Access Only)	T _{CP}		T _C – 5	15		10		6.4		ns
55	Row Address Valid to RAS Assertion (Row Address Setup Time)	t _{ASR}		T _L – 6	4		2		0.1		ns
56	RAS Assertion to ROW Address Not Valid (Row Address Hold Time)	t _{RAH}	slow fast	$\begin{array}{c} 3\times T_C+T_H-\\ 14\\ 2\times T_C+T_H-\\ 14 \end{array}$	56 36		39 24		25.8 14.4		ns ns
57	Column Address Valid to CAS Assertion (Column Address Setup Time)	t _{ASC}		T _L – 6	4		2		0.1		ns
58	CAS Assertion to Column Address Not Valid (Column Address Hold Time)	T _{CAH}	slow fast	$\begin{array}{c} 3\times T_C+T_H-\\ 14\\ 2\times T_C+T_H-\\ 14 \end{array}$	56 36	_	39 24	_	25.8 14.4	_	ns ns
59	Last CAS Assertion to Column Address Not Valid (Column Address Hold Time)	T _{CAH}	slow fast	$7 \times T_C + T_H - 14$ $4 \times T_C + T_H - 14$			100 54		71.2 37.1		ns ns
60	RAS Assertion to Column Address Not Valid	t _{AR}	slow fast	$7 \times T_{C} + T_{H} - 14$ $5 \times T_{C} + T_{H} - 14$			100 69		71.2 48.5		ns ns
61	Column Address Valid to RAS Deassertation	t _{RAL}	slow fast	$\begin{array}{c} 3\times T_{C}+T_{L}-\\ 7\\ 2\times T_{C}+T_{L}-\\ 7\end{array}$	63 43		46 30		32.8 21.2		ns ns
62	\overline{CAS} , \overline{RAS} , \overline{RD} , or \overline{WR} Deassertation to \overline{WR} or \overline{RD} Assertion	t _{RCH} , t _{RRH}	slow fast	$5 \times T_{C} - 11$ $3 \times T_{C} - 11$	89 49		65 35	_	45.8 23.1	_	ns ns
63	CAS or RD Deassertation to Data Not Valid (Data Hold Time)	t _{OFF} , t _{GZ}		0	0		0		0		ns

Table 2-8	External Memory Interface	(EMI) DRAM Timing (Continued)
Table 2-0	External Memory Interface	(EMI) DRAW HIIIII (Conunued)

External Memory Interface (EMI) DRAM Timing

NI-	Characteristics	Chl	Timing	F	50 N	ΛHz	66 MHz		88 MHz		T
No.	Characteristics	Symbol	Mode	Expression	Min	Max	Min	Max	Min	Max	Unit
64	Random Read or Write Cycle Time (Single Access Only)	t _{RC}	slow fast	$\begin{array}{c} 12 \times T_{\rm C} \\ 8 \times T_{\rm C} \end{array}$	240 98.8		182 121	_	136.4 91.0		ns ns
65	WR Deassertation to CAS Assertion	t _{RCS}	slow fast	$\begin{array}{c} 9 \times \mathrm{T_{C}} - 11 \\ 6 \times \mathrm{T_{C}} - 11 \end{array}$	169 109		125 80		91.3 57.2		ns ns
66	CASAssertion to WRDeassertation	t _{WCH}	slow fast	$\begin{array}{c} 3 \times T_{C} - 13 \\ 2 \times T_{C} - 13 \end{array}$	47 27	_	32 17	_	21.1 9.7	_	ns ns
67	Data Valid to CAS Assertion (Data Setup Time)	t _{DS}		T _L – 6	4		2	_	0.1		ns
68	CAS Assertion to Data Not Valid (Data Hold	t _{DH}	slow	$\frac{3\times T_C+T_H-}{14}$	56		39		25.8		ns
	Time)		fast	$\begin{array}{c} 2 \times T_C + T_H - \\ 14 \end{array}$	36		24		14.4		ns
69	RAS Assertion to Data Not Valid	t _{DHR}	slow	$7 imes T_{C} + T_{H} - $ 14	136		100		71.2		ns
			fast	$5\times T_{C}+T_{H}-14$	96		69		48.5		ns
70	WR Assertion to CAS Assertion	t _{WCS}	slow fast	$\begin{array}{c} 4 \times T_{C} - 14 \\ 3 \times T_{C} - 14 \end{array}$	66 46	_	47 31	_	31.4 20.1	_	ns ns
71	WR Assertion Pulse Width (Single Cycle Only)	t _{WP}	slow fast	$7 \times T_{C} - 9$ $5 \times T_{C} - 9$	131 91		97 67	_	70.5 47.8		ns ns
72	RAS Assertion to WR Deassertation (Single Cycle Only)	t _{WCR}	slow fast	$\begin{array}{c} 7 \times T_{C} - 15 \\ 5 \times T_{C} - 15 \end{array}$	125 85		91 61	_	64.5 41.8		ns ns
73	WR Assertion to Data Active		slow	$3 \times T_{C} + T_{H} - $ 13	57		40		26.8		ns
			fast	$\begin{array}{c} 2 \times T_C + T_H - \\ 13 \end{array}$	37	_	25	_	15.4		ns
74	$\overline{\text{RD}}$ or $\overline{\text{WR}}$ Assertion to $\overline{\text{RAS}}$ Deassertation (Single Cycle Only)	t _{ROH} , t _{RWL}	slow fast	$7 \times T_{C} - 13$ $5 \times T_{C} - 13$	127 87		93 63	_	66.5 43.8	_	ns ns
Note	e: 1. n is the number of	successive	accesses. n	= 2, 3, 4, or 6.							

 Table 2-8
 External Memory Interface (EMI) DRAM Timing (Continued)

External Memory Interface (EMI) DRAM Timing

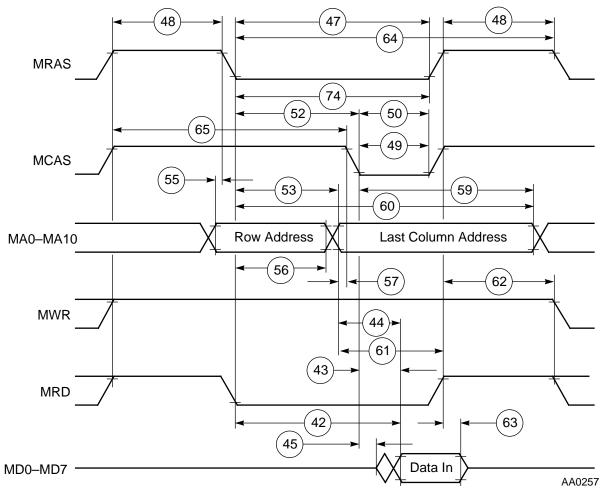


Figure 2-8 DRAM Single Read Cycle

External Memory Interface (EMI) DRAM Timing

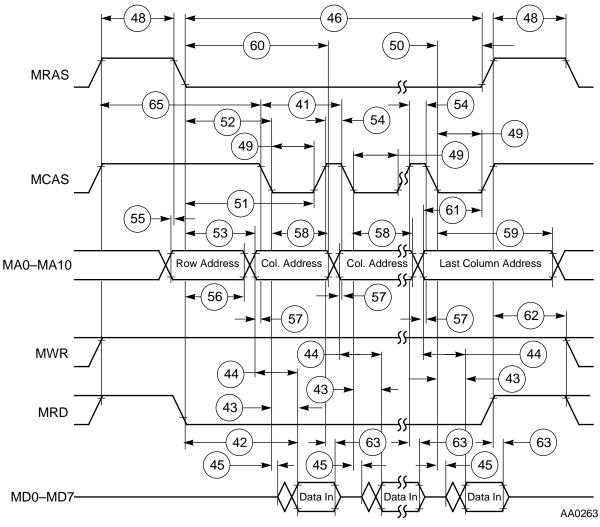


Figure 2-9 DRAM Page Mode Read Cycle

External Memory Interface (EMI) DRAM Timing

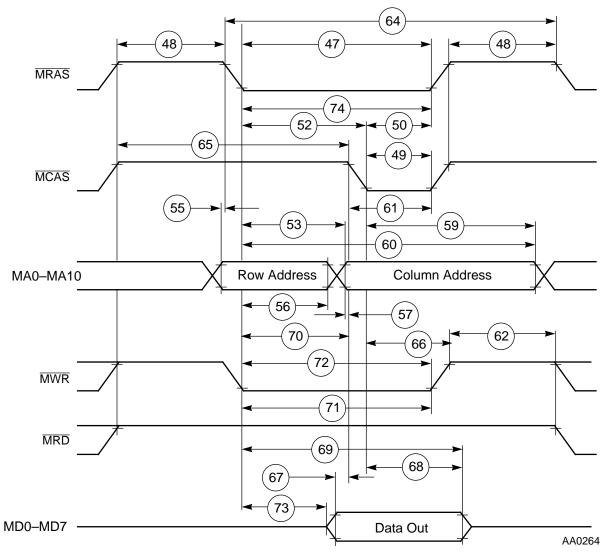


Figure 2-10 DRAM Single Write Cycle

External Memory Interface (EMI) DRAM Timing

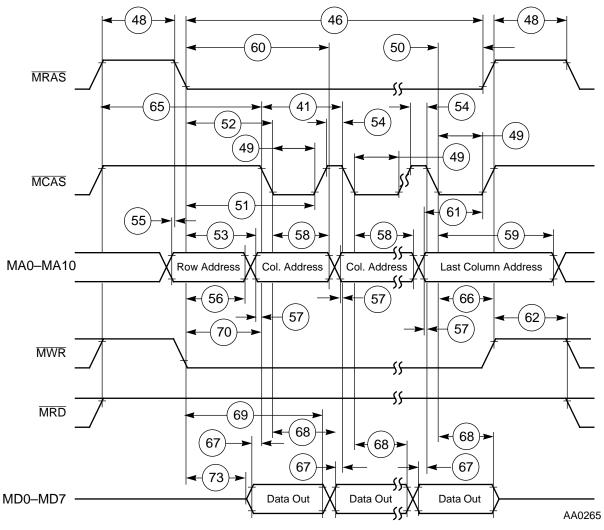


Figure 2-11 DRAM Page Mode Write Cycle

External Memory Interface (EMI) DRAM Refresh Timing

EXTERNAL MEMORY INTERFACE (EMI) DRAM REFRESH TIMING

 $(C_L = 50 pF + 2 TTL Loads)$

Table 2-9 External Memory Interface (EMI) DRAM Refresh Timir	ng
--	----

No.	Characteristics	Sym.	Timing Mode	Evn	50 N	1Hz	66 N	1Hz	88 N	/Hz	Unit
110.	Characteristics	Sym.		Exp.	Min	Max	Min	Max	Min	Max	Unit
81	RAS Deassertation to RAS Assertion	t _{RP}	slow fast	$\begin{array}{c} 6 \times T_{C} - 7 \\ 4 \times T_{C} - 7 \end{array}$	113 73	_	84 54	_	61.2 38.5	_	ns ns
82	CAS Deassertation to CAS Assertion	T _{CPN}	slow fast	$5 \times T_{C} - 7$ $3 \times T_{C} - 7$	93 53	_	71 38	_	49.8 27.1	_	ns ns
83	Refresh Cycle Time	t _{RC}	slow fast	$\begin{array}{c} 13 \times T_{C} \\ 9 \times T_{C} \end{array}$	260 180	_	197 136	_	147.7 102.3	_	ns ns
84	RAS Assertion Pulse Width	t _{RAS}	slow fast	$\begin{array}{c} 7 \times \mathrm{T_C} - 9 \\ 5 \times \mathrm{T_C} - 9 \end{array}$	131 91	_	97 67	_	70.5 47.8	_	ns ns
85	RAS Deassertation to RAS Assertion for Refresh Cycle ¹	t _{RP}	slow fast	$5 \times T_{C} - 5$ $3 \times T_{C} - 5$	95 55	_	70 40		51.8 29.1	_	ns ns
86	CASAssertion to RASAssertion on RefreshCycle	T _{CSR}		T _C – 7	13	_	8	_	4.4	_	ns
87	RAS Assertion to CAS Deassertation on Refresh Cycle	T _{CHR}	slow fast	$7 \times T_{\rm C} - 15$ $5 \times T_{\rm C} - 15$	125 85	_	91 61	_	64.5 41.8	_	ns ns
88	RAS Deassertation to CAS Assertion on a Refresh Cycle	t _{RPC}	slow fast	$5 \times T_{\rm C} - 11$ $3 \times T_{\rm C} - 11$	89 49	_	65 34	_	45.8 23.1	_	ns ns
89	CAS Deassertation to Data Not Valid	t _{OFF}		0	0		0		0		ns
Note:	1. This happens when	a Refresh (Cycle is follo	wed by an Acce	ess Cyc	le.					

External Memory Interface (EMI) SRAM Timing

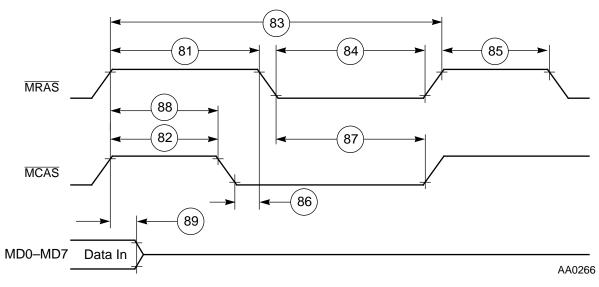


Figure 2-12 \overline{CAS} before \overline{RAS} Refresh Cycle

EXTERNAL MEMORY INTERFACE (EMI) SRAM TIMING

 $(C_L = 50 pF + 2 TTL Loads)$

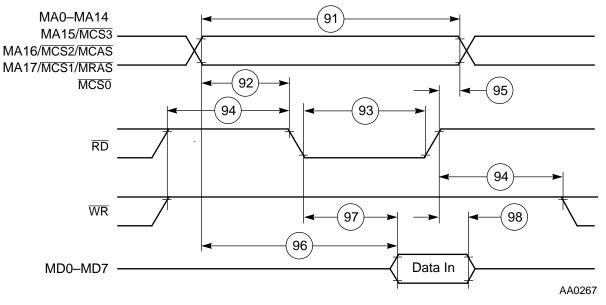
Table 2-10	External Memory Interface (EMI) SRAM Timing
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No.	Characteristics	Symbol	Expression	50 N	ИНz	66 N	ИНz	88 N	1Hz	Unit
110.	Characteristics	Symbol	Expression	Min	Max	Min	Max	Min	Max	
91	Address Valid and \overline{CS} Assertion Pulse Width	t _{RC} , t _{WC}	$\begin{array}{c} 4 \times T_C - 11 + \\ Ws \times T_C \end{array}$	69	_	50		34.5		ns
92	Address Valid to $\overline{\text{RD}}$ or $\overline{\text{WR}}$ Assertion	t _{AS}	$T_{C} + T_{L} - 13$	17	_	10		4.4		ns
93	RD or WR Assertion Pulse Width	t _{WP}	$\begin{array}{c} 2 \times T_C - 5 + \\ Ws \times T_C \end{array}$	35		23		17.7		ns
94	$\overline{\text{RD}}$ or $\overline{\text{WR}}$ Deassertation to $\overline{\text{RD}}$ or $\overline{\text{WR}}$ Assertion	_	$2 imes T_{C}$ – 11	29	_	19	_	11.7	_	ns
95	RD or WR Deassertation to Address not Valid	t _{WR}	$T_H - 6$	4	-	2	_	0.1	—	ns
96	Address Valid to Input Data Valid	t_{AA}, t_{AC}	$\begin{array}{c} 3 \times \mathrm{T_C} + \mathrm{T_L} - 15 + \\ \mathrm{Ws} \times \mathrm{T_C} \end{array}$	_	55	_	38	_	24.8	ns
97	RD Assertion to Input Data Valid	t _{OE}	$\begin{array}{c} 2 \times T_C \text{ - } 15 \text{ +} \\ Ws \times T_C \end{array}$	_	25	_	15		7.7	ns
98	RD Deassertation to Data Not Valid (Data Hold Time)	t _{OHZ}	0	0		0		0		ns

External Memory Interface (EMI) SRAM Timing

No.	Characteristics	Symbol	Expression	50 MHz		66 MHz		88 N	Unit	
110.	Characteristics			Min	Max	Min	Max	Min	Max	Umt
99	Address Valid to WR Deassertation	T _{CW} , t _{AW}	$\begin{array}{c} 3 \times T_C + T_L - 14 + \\ Ws \times T_C \end{array}$	56		39		25.8		ns
100	Data Setup Time to WR Deassertation	t _{DS} (t _{DW})	$\begin{array}{c} T_{C} + T_{L} - 5 + \\ Ws \times T_{C} \end{array}$	25	_	18	—	12.0	_	ns
101	Data Hold Time from \overline{WR} Deassertation	t _{DH}	$T_H - 6$	4	—	2	—	0.1	_	ns
102	WR Assertion to Data Valid	—	T _H + 4	—	14	_	12	_	9.7	ns
	WR Deassertation to Data high impedance ¹		T _H + 10	_	20	_	18	_	15.7	ns
104	WR Assertion to Data Active	_	$T_H - 6$	4	_	2	_	0.1	_	ns

 Table 2-10
 External Memory Interface (EMI) SRAM Timing





External Memory Interface (EMI) SRAM Timing

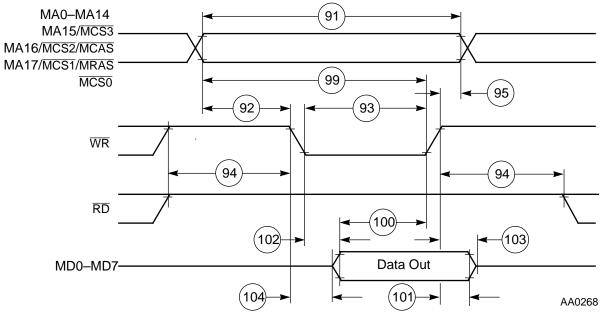


Figure 2-14 SRAM Write Cycle

Serial Audio Interface (SAI) Timing

123 Word Select In Valid to SCKT

Edge (WST In Set-up Time) 124 SCKT Edge to Word Select In

Not Valid (WST In Hold Time)

SERIAL AUDIO INTERFACE (SAI) TIMING

 $(C_L = 50 pF + 2 TTL Loads)$

		Serial	Audio Internace (SAI)		ig		-		-
No.	Characteristics	Mode	Europeien	50 N	ΛHz	66 N	ИНz	81 MHz		Unit
INO.	Characteristics	Mode	Expression	Min	Max	Min	Max	Min	Max	Unit
111	Minimum Serial Clock Cycle = t _{SAICC} (min)	master slave	$\begin{array}{c} 4\times T_{C} \\ 3\times T_{C}+5 \end{array}$	80 65	_	61 51	_	45.5 39.1		ns ns
112	Serial Clock High Period	master slave	$\begin{array}{c} 0.5 \times t_{\rm SAICC} - 8 \\ 0.35 \times t_{\rm SAICC} \end{array}$	32 23		22 18	_	14.7 13.7	_	ns ns
113	Serial Clock Low Period	master slave	$\begin{array}{c} 0.5 \times t_{\rm SAICC} - 8 \\ 0.35 \times t_{\rm SAICC} \end{array}$	32 23	_	22 18	_	14.8 13.7	_	ns ns
114	Serial Clock Rise/Fall Time	master slave	$\frac{8}{0.15 \times t_{\rm SAICC}}$	_	8 10	_	8 8	_	8.0 5.9	ns ns
115	Data In Valid to SCKR edge (Data In Set-up Time)	master slave	26 4	26 4		26 4	_	26 4		ns ns
116	SCKR Edge to Data In Not Valid (Data In Hold Time)	master slave	0 14	0 14	_	0 14	_	0 14	_	ns ns
117	SCKR Edge to Word Select Out Valid (WSR Out Delay Time)	master	20	-	20	-	20	_	20	ns
118	Word Select In Valid to SCKR Edge (WSR In Set-up Time)	slave	12	12	_	12	_	12	_	ns
119	SCKR Edge to Word Select In Not Valid (WSR In Hold Time)	slave	12	12	_	12	_	12	_	ns
121	SCKT Edge to Data Out Valid (Data Out Delay Time)	master slave ¹ slave ²	13 40 T _H + 34		13 40 44		13 40 41		13 40 39.7	ns ns ns
122	SCKT Edge to Word Select Out Valid (WST Out Delay Time)	master	19		19		19		19	ns
	1 • • • • • • • • • • • • •			1	1	1	1		1	

slave

slave

When the Frequency Ratio between Parallel and Serial clocks is 1:4 or greater

When the Frequency Ratio between Parallel and Serial clocks is 1:3 - 1:4

Table 2-11	Serial Audio Interface (SAI) Timing
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12

12

12

12

12

12

12

12

ns

ns

Note:

1.

2.

Serial Audio Interface (SAI) Timing

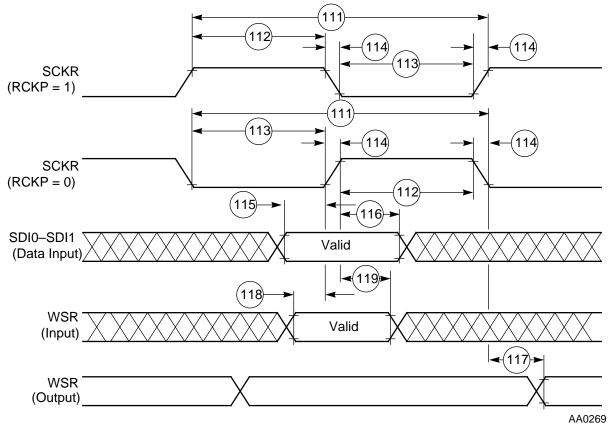
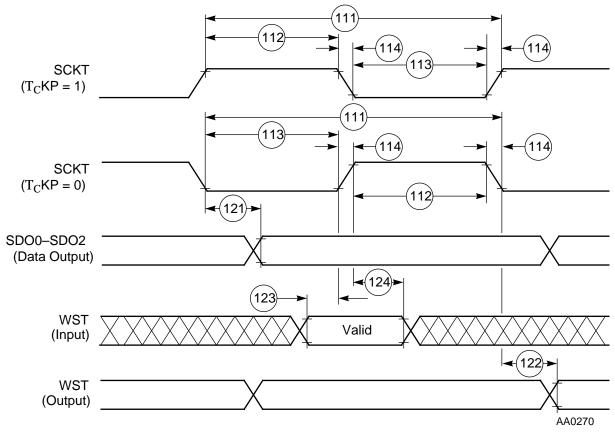
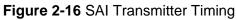


Figure 2-15 SAI Receiver Timing

Serial Audio Interface (SAI) Timing





SERIAL HOST INTERFACE (SHI) SPI PROTOCOL TIMING

(C_L = 50 pF; V_{IHS} = $0.7 \times V_{CC}$, V_{ILS} = $0.3 \times V_{CC}$)

No.	Characteristics	Mode	Filter	Expression	50 N	/Hz	66 N	/IHz	88 M	lHz	Unit
			Mode	•	Min	Max	Min	Max	Min	Max	
	Tolerable Spike Width		bypassed		—	0		0	_	0	ns
	on Clock or Data In		narrow			20		20	—	20	ns
			wide		—	100	—	100	—	100	ns
141	Minimum Serial Clock										
	$Cycle = t_{SPICC}(min)$										
	For frequency below 33										
	MHz ¹	master	bypassed	$4 \times T_C$	—	—	—	—	—	—	ns
	For frequency above 33										
	MHz ¹		bypassed	$6 imes T_{C}$	120	—	91	—	68.2	—	ns
			narrow	1000	1000	—	1000	—	1000	—	ns
	$CPHA = 0, CPHA = 1^2$		wide	2000	2000	—	2000	—	2000	—	ns
		slave	bypassed	$3 imes T_{C}$	60	—	45	—	34.1		ns
			narrow	$3 \times T_{C} + 25$	85	—	70	—	59.1	—	ns
	CPHA = 1		wide	$3 imes T_{C}$ + 85	145	—	130	—	119.1	—	ns
		slave	bypassed	$3 imes T_{C}$ + 79	139	—	124	—	113.1	—	ns
			narrow	$3 imes T_{C} + 431$	491	—	476	—	465.1	—	ns
			wide	$3 \times T_{C} + 1022$	1082		1067		1056.1	—	ns
142	Serial Clock High Period CPHA = 0 , CPHA = 1^2	master		$0.5 \times t_{SPICC}$ –10	50	_	35	_	24.1	_	ns
		slave	bypassed	T _C + 8	28	—	23	_	19.4	—	ns
			narrow	T _C + 31	51	—	46	_	42.4	—	ns
	CPHA = 1		wide	$T_{C} + 43$	63	—	58	_	54.4	—	ns
		slave	bypassed	$T_{C} + T_{H} + 40$	70	—	63	—	57.0	—	ns
			narrow	$T_{C} + T_{H} + 216$	246		239		233.0		ns
			wide	$T_{C} + T_{H} + 511$	541		534	_	528.0		ns
143	Serial Clock Low Period CPHA = 0, CPHA = 1^2	master		$0.5 \times t_{SPICC}$ –10	50	_	35	_	24.1	_	ns
		slave	bypassed	T _C + 8	28		23	—	19.4		ns
			narrow	$T_{C} + 31$	51		46	—	42.4		ns
	CPHA = 1		wide	$T_{C}^{\circ} + 43$	63	_	58	_	54.4	_	ns
		slave	bypassed	$T_{C} + T_{H} + 40$	70	_	63	_	57.0	_	ns
			narrow	$T_{C} + T_{H} + 216$	246	—	239		233.0	_	ns
			wide	$T_{C}^{0} + T_{H}^{1} + 511$	541		534		528.0		ns
144	Serial Clock Rise/Fall	master		10	-	10		10		10	ns
	Time	slave		2000		2000		2000		2000	ns

Table 2-12	Serial Host Interface (SHI) SPI Protocol Timing
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			Filter		50 N	ИНz	66 N	ИНz	88 MHz		
No.	Characteristics	Mode	Mode	Expression	Min	Max	Min	Max	Min	Max	Unit
146	SS Assertion to FirstSCK Edge CPHA = 0CPHA = 1	slave slave	bypassed narrow wide bypassed narrow wide	$\begin{array}{c} T_{C}+T_{H}+35\\ T_{C}+T_{H}+35\\ T_{C}+T_{H}+35\\ 6\\ 0\\ 0\\ 0\\ \end{array}$	65 65 65 6 0 0		58 58 58 6 0 0		52.0 52.0 52.0 6 0 0		ns ns ns ns ns ns ns
147	Last SCK Edge to \overline{SS} Not Asserted CPHA = 0 CPHA = 1^3	slave slave	bypassed narrow wide bypassed narrow wide	$\begin{array}{c} T_{C}+6\\ T_{C}+70\\ T_{C}+197\\ 2\\ 66\\ 193 \end{array}$	26 90 217 2 66 193		21 85 212 2 66 193		17.4 81.4 208.4 2 66 193		ns ns ns ns ns ns
148	Data In Valid to SCK Edge (Data In Set-up Time)	master	bypassed narrow wide	0 MAX {(37 -T _C), 0} MAX {(52 -T _C), 0} 0 MAX {(38 -T _C), 0}	0 17 32	_	0 22 37	_	0 25.6 40.6		ns ns ns
		slave	bypassed narrow wide	MAX { $(53 - T_C), 0$ }	0 18 33	 	0 23 38		0 26.6 41.6	 	ns ns ns
149	SCK Edge to Data In Not Valid (Data In Hold Time)	master slave	bypassed narrow wide bypassed narrow wide	$\begin{array}{c} 2 \times T_{C} + 17 \\ 2 \times T_{C} + 18 \\ 2 \times T_{C} + 28 \\ 2 \times T_{C} + 17 \\ 2 \times T_{C} + 17 \\ 2 \times T_{C} + 18 \\ 2 \times T_{C} + 28 \end{array}$	57 58 68 57 58 68		47 48 58 47 48 58		39.7 40.7 50.7 39.7 40.7 50.7		ns ns ns ns ns ns
150	SS Assertion to Data Out Active	slave		4	4	—	4	_	4	_	ns
151	SS Deassertation to Data high impedance ⁴	slave		24	_	24	_	24	_	24	ns
152	SCK Edge to Data Out Valid (Data Out Delay Time) CPHA = 0, CPHA = 1 ²	master slave	bypassed narrow wide bypassed narrow	41 214 504 41 214		41 214 504 41 214		41 214 504 41 214	 	41 214 504 41 214	ns ns ns ns ns
	CPHA = 1	slave	wide bypassed narrow wide	$504 \\ T_{C} + T_{H} + 40 \\ T_{C} + T_{H} + 216 \\ T_{C} + T_{H} + 511$		504 70 246 541		504 63 239 534	 	504 57.0 233 528	ns ns ns ns

					50 N	ИНz	66 N	/Hz	88 M	1117	
No.	Characteristics	Mode	Filter Mode	Expression							Unit
			Mode		Min	Max	Min	Max	Min	Max	
153	SCK Edge to Data Out Not Valid (Data Out Hold Time)	master slave	bypassed narrow wide bypassed narrow wide	0 57 163 0 57 163	0 57 163 0 57 163		0 57 163 0 57 163		0 57 163 0 57 163		ns ns ns ns ns ns
154	$\overline{\text{SS}}$ Assertion to Data Out Valid CPHA = 0	slave		$T_{\rm C} + T_{\rm H} + 35$	_	65		58	_	52.0	ns
157	First SCK Sampling Edge to HREQ Output Deassertation	slave	bypassed narrow wide	$\begin{array}{c} 3\times T_{C}+T_{H}+32\\ 3\times T_{C}+T_{H}+209\\ 3\times T_{C}+T_{H}+507 \end{array}$		102 279 577		85 262 560		71.8 248.8 546.8	ns ns ns
158	Last SCK Sampling Edge to HREQ Output Not Deasserted CPHA = 1	slave	bypassed narrow wide	$\begin{array}{c} 2\times T_{C}+T_{H}+6\\ 2\times T_{C}+T_{H}+63\\ 2\times T_{C}+T_{H}+169 \end{array}$	56 113 219		44 101 207		34.4 91.4 197.4		ns ns ns
159	SS Deassertation to HREQ Output Not Deasserted CPHA = 0	slave		$2 \times T_{\rm C} + T_{\rm H} + 7$	57		45		35.4		ns
160	SSDeassertation PulseWidth CPHA = 0	slave		T _C + 4	24		19		15.4	_	ns
161	HREQ In Assertion to First SCK Edge	master		$\begin{array}{c} 0.5 \times t_{SPICC} + \\ 2 \times T_{C} + 6 \end{array}$	106	_	82	_	62.8	_	ns
162	HREQ In Deassertation to Last SCK Sampling Edge (HREQ In Set-up Time) CPHA = 1	master		0	0		0		0		ns
163	First SCK Edge to HREQ In Not Asserted (HREQ In Hold Time)	master		0	0		0		0	_	ns
Note	 ratio is 4:1. For an Im Clock frequency rational 2. In CPHA = 1 mode, written at least T_C n transfers at t_{SPICC} = SCK of each word. 	ternal Clo o is 6:1. the SPI s is before t $3 \times T_C$, i	ck frequency lave supports he first edge f the user ass	Hz, the minimum peri above 33 MHz, the mi s data transfers at t _{SPIC} of SCK of each word.I ures that the HTX is v active low between su	nimun _{CC} = 3 n CPH vritten	n perm $\times T_{C}$, i $A = 1$ at leas	issible if the u mode, st T _C n	Interna ser ass the SP	al Clock sures tha [slave si	to Seria at the H upports	al ITX is s data

Table 2-12 Serial Host Interface (SHI) SPI Protocol Timing (Continued)

3. When CPHA = 1, the \overline{SS} line may remain active low between successive transfers.

4. Periodically sampled, not 100% tested

5. Refer to the *DSP56007 User's Manual* for a detailed description of how to use the different filtering modes.

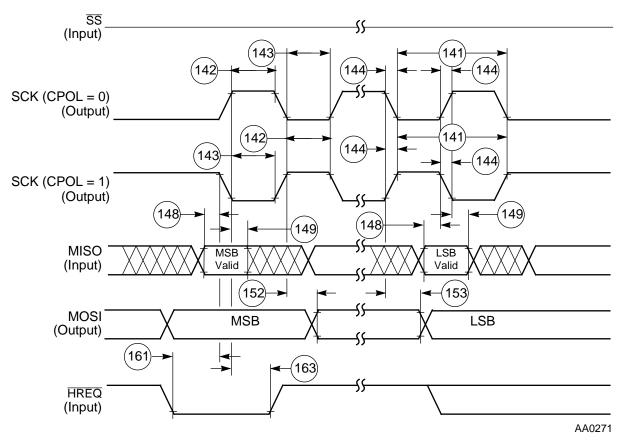


Figure 2-17 SPI Master Timing (CPHA = 0)

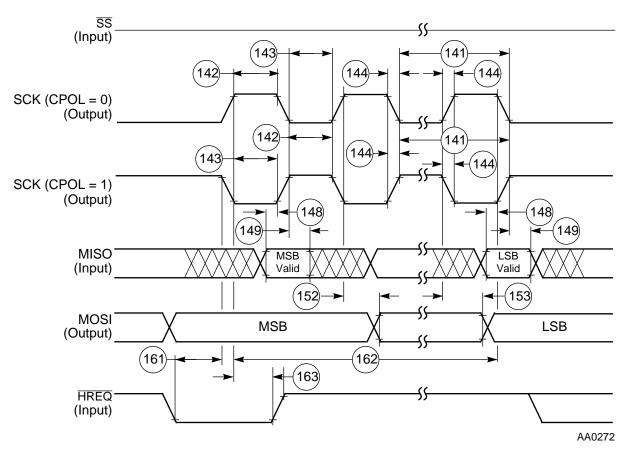


Figure 2-18 SPI Master Timing (CPHA = 1)

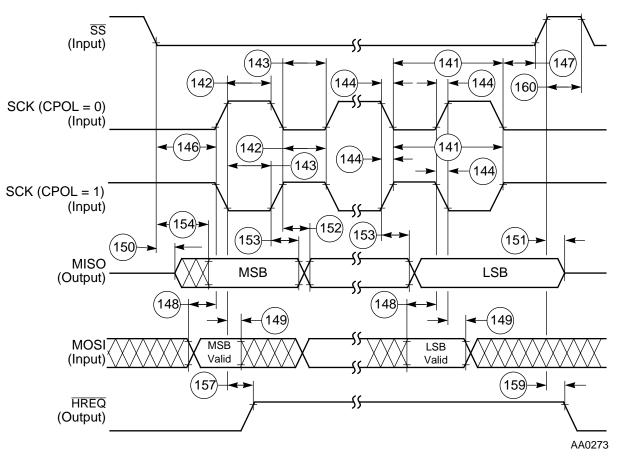
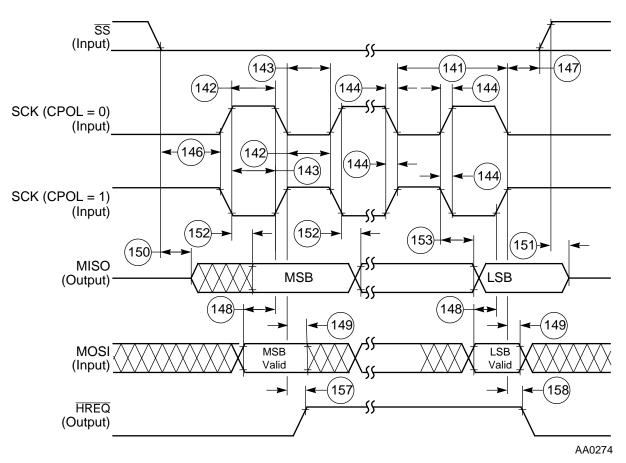
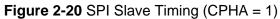


Figure 2-19 SPI Slave Timing (CPHA = 0)





SERIAL HOST INTERFACE (SHI) I²C PROTOCOL TIMING

 $(V_{IHS} = 0.7 \times V_{CC}, V_{ILS} = 0.3 \times V_{CC})$

 $(V_{OHS} = 0.8 \times V_{CC}, V_{OLS} = 0.2 \times V_{CC})$

 $(R_P (min) = 1.5 \text{ k}\Omega)$

Table 2-15 SHITC Protocol Hilling	Table 2-13	SHI I ² C Protocol Timing
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	Standard I ² ((C _L = 400 pF, R _P = 2 k				
NI			All free	T	
No.	Characteristics	Symbol	Min	Max	Unit
	Tolerable Spike Width on SCL or SDA Filters Bypassed Narrow Filters Enabled Wide Filters Enabled			0 20 100	ns ns ns
171	Minimum SCL Serial Clock Cycle	t _{SCL}	10.0	—	μs
172	Bus Free Time	t _{BUF}	4.7	_	μs
173	Start Condition Set-up Time	t _{SU;STA}	4.7	_	μs
174	Start Condition Hold Time	t _{HD;STA}	4.0	_	μs
175	SCL Low Period	t _{LOW}	4.7	_	μs
176	SCL High Period	t _{HIGH}	4.0	_	μs
177	SCL and SDA Rise Time	t _r	_	1.0	μs
178	SCL and SDA Fall Time	t _f	_	0.3	μs
179	Data Set-up Time	t _{SU;DAT}	250	_	ns
180	Data Hold Time	t _{HD;DAT}	0.0	—	ns
182	SCL Low to Data Out Valid	t _{VD;DAT}	_	3.4	μs
183	Stop Condition Set-up Time	t _{SU;STO}	4.0	_	μs
Note:	Refer to the <i>DSP56007 User's Manual</i> for a detail modes.	ed description of how to	o use the c	lifferent fil	tering

The Programmed Serial Clock Cycle, t_{I^2CCP} , is specified by the value of the HDM5–HDM0 and HRS bits of the HCKR (SHI Clock control Register).

The expression for t_{I^2CCP} is:

 $t_{I^2CCP} = [Tc \times 2 \times (HDM[5:0] + 1) \times (7 \times (1 - HRS) + 1)]$

where

- HRS is the Prescaler Rate Select bit. When HRS is cleared, the fixed divide-byeight prescaler is operational. When HRS is set, the prescaler is bypassed.
- HDM5-HDM0 are the Divider Modulus Select bits.
- A divide ratio from 1 to 64 (HDM5–HDM0 = 0 to \$3F) may be selected.

In I²C mode, you may select a value for the Programmed Serial Clock Cycle from $6 \times T_{C}$ (HDM5–HDM0 = 2, HRS = 1) to

$0 \times 1_{\rm C}$	$(\Pi D N D - \Pi D N D = 2, \Pi K S = 1)$	to
$1024 \times T_{\rm C}$	(HDM5-HDM0 = \$3F, HRS = 0).	

The DSP56007 provides an improved I^2C bus protocol. In addition to supporting the 100 kHz I^2C bus protocol, the SHI in I^2C mode supports data transfers at up to 1000 kHz. The actual maximum frequency is limited by the bus capacitances (C_L),the pull-up resistors (R_P), (which affect the rise and fall time of SDA and SCL, (see table below)), and by the input filters.

Consideration for programming the SHI Clock Control Register (HCKR)—Clock Divide Ratio: the master must generate a bus free time greater than T172 slave when operating with a DSP56007 SHI I²C slave.

The table below describes a few examples:

	Cond	itions to be	Resi	Resulting Limitations				
Bus Load	Master Oper- ating Freq.	Slave Oper- ating Freq.	Master Filter Mode	Slave Filter Mode	T172 Slave	Min. Perm- issible t _{I'CCP}	T172 Master	Maximum I ² C Serial Frequency
$C_{L} = 50 \text{ pF},$ $R_{P} = 2 \text{ k}\Omega$	88 MHz	88 MHz	Bypassed Narrow Wide	Bypassed Narrow Wide	36 ns 60 ns 95 ns	$\begin{array}{c} 56 \times T_{C} \\ 60 \times T_{C} \\ 66 \times T_{C} \end{array}$	41 ns 66 ns 103 ns	1010 kHz 825 kHz 634 kHz

 Table 2-14
 Considerations for Programming the SHI Clock control Register (HCKR)

Example: for $C_L = 50$ pF, $R_P = 2$ k Ω , f = 88 MHz, Bypassed Filter mode: The master, when operating with a DSP56007 SHI I²C slave with an 88 MHz operating frequency, must generate a bus free time greater than 36 ns (T172 slave). Thus, the minimum permissible t_{I^2CCP} is $56 \times T_C$ which gives a bus free time of at least 41 ns (T172 master). This implies a maximum I²C serial frequency of 1010 kHz.

In general, bus performance may be calculated from the C_L and R_P of the bus, the Input Filter modes and operating frequencies of the master and the slave. **Table 2-15** contains the expressions required to calculate all relevant performance timing for a given C_L and R_P .

			Imp	oroved I ² C (C	$C_L = 50 \text{ pF}, R_P = 2 \text{ k}$	Ω)						
				T.1.		50 N	1Hz ²	66 N	1Hz ³	88 M	(Hz ⁴	U
No.	Char.	Sym.	Mode	Filter Mode	Expression	Min	Max	Min	Max	Min	Max	n i t
	Tolerable Spike Width on SCL or SDA			bypassed narrow wide	0 20 100		0 20 100		0 20 100		0 20 100	ns ns ns
171	SCL Serial Clock Cycle	t _{SCL}	master	bypassed narrow	$\begin{array}{c} t_{I^{c}CCP}+3\times T_{C}+\\ 72+t_{r}\\ t_{I^{c}CCP}+3\times T_{C}+\\ 245+t_{r} \end{array}$	1050 1263		1007 1225	_	981 1199	_	ns ns
				wide bypassed	$\begin{array}{c} t_{I^{c}CCP}+3\times T_{C}+\\ 535+t_{r}\\ 4\times T_{C}+T_{H}+ \end{array}$	1593 500	_	1591 478	_	1557 461	 	ns ns
			slave	narrow wide	$\begin{array}{c} 172 + t_{r} \\ 4 \times T_{C} + T_{H} + \\ 366 + t_{r} \\ 4 \times T_{C} + T_{H} + \\ 648 + t_{r} \end{array}$	694 976		672 954	_	655 937	_	ns ns
172	Bus Free Time	t _{BUF}	master	bypassed narrow	$\begin{array}{c} 0.5 \times t_{I^{\prime}CCP} - \\ 42 - t_{r} \\ 0.5 \times t_{I^{\prime}CCP} - \end{array}$	60 80		46 68		38.2 60.9	_	ns ns
				wide	$\begin{array}{c c} 42 - t_r \\ 0.5 \times t_{I^*CCP} - \\ 42 - t_r \end{array}$	100	_	102	_	95	_	ns
			slave	bypassed narrow wide	$\begin{array}{c} 2\times T_{C}+11\\ 2\times T_{C}+35\\ 2\times T_{C}+70\end{array}$	51 75 110		41 65 100		33.7 57.7 92.7	— — —	ns ns ns
173	Start Condition Set-up Time	t _{SU;STA}	slave	bypassed narrow wide	12 50 150	12 50 150		12 50 150		12 50 150		ns ns ns

Table 2-15SHI Improved I²C Protocol Timing

			Imp	proved I ² C (C	$C_{\rm L} = 50 \ {\rm pF}, \ {\rm R}_{\rm P} = 2 \ {\rm ks}^{-1}$	Ω)						
						50 MHz ²		66 N	1Hz ³	88 M	IHz ⁴	U
No.	Char.	Sym.	Mode	Aode Filter Mode	Expression	Min	Max	Min	Max	Min	Max	n i t
174	Start Condition Hold Time	t _{HD;STA}	master	bypassed	$0.5 \times t_{I'CCP} + 12 - t_f$	332	—	318	—	310	—	ns
				narrow	$\begin{array}{c c} 12 & t_{f} \\ 0.5 \times t_{I'CCP} + \\ 12 - t_{f} \end{array}$	352	-	340	_	333	_	ns
				wide	$\begin{array}{c c} 0.1 & t_{I} \\ 0.5 \times t_{I^{2}CCP} + \\ 12 - t_{f} \end{array}$	372	-	378	_	367	_	ns
			slave	bypassed narrow wide	$\begin{array}{c} 2 \times T_{C} + T_{H} + 21 \\ 2 \times T_{C} + T_{H} + 100 \\ 2 \times T_{C} + T_{H} + 200 \end{array}$	71 150 250	 	59 138 238		49.4 128 228	 	ns ns ns
175	SCL Low Period	t _{LOW}	master	bypassed	$0.5 \times t_{I^2CCP} + 18 - t_f$	338		324		316	_	ns
				narrow	$\begin{array}{c} 0.5 \times t_{I^{2}CCP} + \\ 18 - t_{f} \end{array}$	358		346	_	339	_	ns
				wide	$0.5 \times t_{I^{2}CCP} + 18 - t_{f}$	378		384	_	373	-	ns
			slave	bypassed	$2 \times T_{C} + 74 + t_{r}$	352		342		335	_	ns
				narrow	$2 \times T_{C} + 286 + t_{r}$	564		554		534	-	ns
				wide	$2 \times T_{C} + 586 + t_{r}$	864		854		847		ns
176	SCL High Period	t _{HIGH}	master	bypassed	$ \begin{vmatrix} 0.5 \times t_{I^2CCP} + 2 \times \\ T_C + 19 \end{vmatrix} $	379	-	375		360	_	ns
				narrow	$\begin{array}{c} 0.5 \times t_{I^{2}CCP} + \\ 2 \times T_{C} + 144 \end{array}$	544	-	523		507	_	ns
				wide	$\begin{array}{c} 0.5 \times t_{I^{2}CCP} + \\ 2 \times T_{C} + 356 \end{array}$	776	-	773		754	_	ns
			slave	bypassed	$2 \times T_{C} + T_{H} - 1$	49		37	—	27.4	-	ns
				narrow wide	$\begin{vmatrix} 2 \times T_{\rm C} + T_{\rm H} + 18 \\ 2 \times T_{\rm C} + T_{\rm H} + 30 \end{vmatrix}$	68 80		56 68		46.4 58.4		ns ns
177	SCL Rise Time Output ¹	t _r			$1.7 \times R_P \times$		238		238		238	ns
	Input				(C _L + 20) 2000	_	2000	_	2000	_	2000	ns
178	SCL Fall Time Output ¹	t _f			$20 + 0.1 \times (C_L - 50)$	_	20	_	20		20	ns
	Input				2000		2000		2000	_	2000	ns
179	Data Set-up Time	t _{SU;DAT}		bypassed	T _C + 8	28		23	—	19.4	-	ns
				narrow wide	$T_{C} + 60$ $T_{C} + 74$	80 94		75 89	$ $	71.4 85.4		ns ns
				wide	T _C + 74	94		89		85.4		

 Table 2-15
 SHI Improved I²C Protocol Timing (Continued)

			Imp	proved I ² C (C	$C_{\rm L} = 50 \rm pF, R_{\rm P} = 2 \rm ks$	Ω)						
			-				1Hz ²	66 N	1Hz ³	2 ³ 88 MHz ⁴		U
No.	Char.	Sym.	Mode	Filter Mode	Expression	Min	Max	Min	Max	Min	Max	n i t
180	Data Hold Time	t _{HD;DAT}		bypassed narrow wide	0 0 0	0 0 0		0 0 0		0 0 0		ns ns ns
182	SCL Low to Data Out Valid	t _{VD;DAT}		bypassed narrow wide	$\begin{array}{c} 2\times T_C+71+t_r\\ 2\times T_C+244+t_r\\ 2\times T_C+535+t_r \end{array}$		349 522 813		339 512 803		332 505 796	ns ns ns
183	Stop Condition Set-up Time	t _{SU;STO}	master slave	bypassed narrow wide bypassed narrow wide	$\begin{array}{c} 0.5 \times t_{I^{'}CCP} + \\ T_{C} + T_{H} + 11 \\ 0.5 \times t_{I^{'}CCP} + \\ T_{C} + T_{H} + 69 \\ 0.5 \times t_{I^{'}CCP} + \\ T_{C} + T_{H} + 183 \\ 11 \\ 50 \\ 150 \end{array}$	381 459 613 11 50 150		359 440 592 11 50 150		346 427 575 11 50 150		ns ns ns ns ns ns
184	HREQ In Deassertation to Last SCL Edge (HREQ In Set-up Time)		master	bypassed narrow wide	0 0 0	0 0 0	 	0 0 0	 	0 0 0		ns ns ns
186	First SCL Sampling Edge to HREQ Output Deassertation		slave	bypassed narrow wide	$\begin{array}{c} 3\times T_{C}+T_{H}+32\\ 3\times T_{C}+T_{H}+209\\ 3\times T_{C}+T_{H}+507 \end{array}$		102 279 577		85 262 560	 	72 249 547	ns ns ns
187	Last SCL Edge to HREQ Output Not Deasserted		slave	bypassed narrow wide	$\begin{array}{c} 2\times T_C+T_H+6\\ 2\times T_C+T_H+63\\ 2\times T_C+T_H+169 \end{array}$	56 113 219		44 101 207		34.4 91.4 197.4		ns ns ns
188	HREQ In Assertion to First SCL Edge		master	bypassed narrow wide	$ \begin{array}{c} t_{I^{\prime}CCP}+2\times T_{C}+6\\ t_{I^{\prime}CCP}+2\times T_{C}+6\\ t_{I^{\prime}CCP}+2\times T_{C}+6 \end{array} \end{array} $	766		688 733 809		665 711 779		ns ns ns
189	First SCL Edge to HREQ In Not Asserted (HREQ In Hold Time)		master		0	0	_	0		0		ns

Table 2-15 SHI Improved I²C Protocol Timing (Continued)

		Char.	Sym.		T *1.	Expression	50 N	1Hz ²	66 MHz ³		88 MHz ⁴		U	
No.				Mode	Filter Mode		Min	Max	Min	Max	Min	Max	n i t	
Note:	1. 2. 3.	Bypassed F A t_{I^*CCP} of Narrow Fil A t_{I^*CCP} of Filter mode A t_{I^*CCP} of Bypassed F A t_{I^*CCP} of Narrow Fil A t_{I^*CCP} of Bypassed F A t_{I^*CCP} of Bypassed F A t_{I^*CCP} of Narrow Fil A t_{I^*CCP} of Narrow Fil A t_{I^*CCP} of	$34 \times T_{C} \text{ (th}$ ilter mode. $36 \times T_{C} \text{ (th}$ ter mode. $40 \times T_{C} \text{ (th}$ ilter mode. $43 \times T_{C} \text{ (th}$ ilter mode. $51 \times T_{C} \text{ (th}$ ister mode. $56 \times T_{C} \text{ (th}$ ilter mode. $60 \times T_{C} \text{ (th}$ ter mode. $60 \times T_{C} \text{ (th}$ iter mode. $60 \times T_{C} \text{ (th}$	e maximu ne maximu ne maximu ne maximu ne maximu ne maximu ne maximu	m permitted fo um permitted f um permitted f m permitted fo um permitted f um permitted f um permitted fo um permitted fo	or the given bus load) for the given bus load for the given bus load or the given bus load for the given bus load for the given bus load or the given bus load for the given bus load	d) was d) was was us d) was d) was was us d) was	used for ed for used fo used fo ed for used fo	or the o or the cal- or the cal- or the c the cal- or the cal-	calcula calcula culatio calcula calcula culatio calcula	tions ir tions ir ns in th tions ir tions ir ns in th tions ir	n the n the W e n the n the W e n the	/id	
	5.	Filter mode Refer to the modes.		007 Use	r's Manual fo	or a detailed descript	ion of l	now to	use th	e diffe	rent fil	tering		

Table 2-15	SHI Improved I ² C Protocol Timing (Continued	Ð
	Sin improved i e i totocoi i ining (continued	•

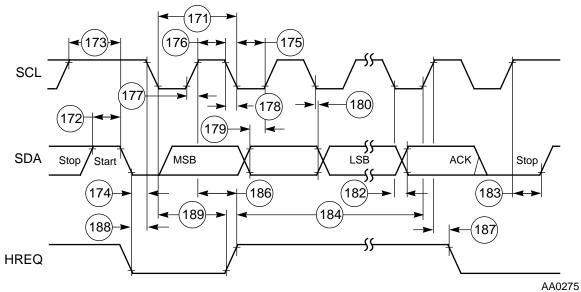


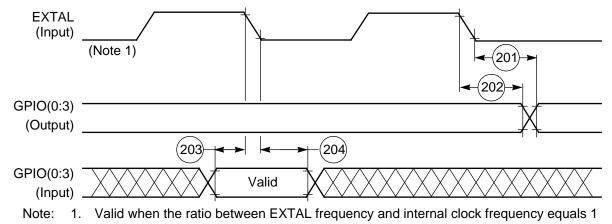
Figure 2-21 I²C Timing

General Purpose I/O (GPIO) Timing

GENERAL PURPOSE I/O (GPIO) TIMING

 $(C_L = 50 \text{ pF} + 2 \text{ TTL Loads})$

No.	Characteristics Expressi		50/66/8	8 MHz	Unit
110.	Characteristics	Expression	Min	Max	Unit
201	EXTAL Edge to GPIO Out Valid (GPIO Out Delay Time)	26	_	26	ns
202	EXTAL Edge to GPIO Out Not Valid (GPIO Out Hold Time)	2	2	_	ns
203	GPIO In Valid to EXTAL Edge (GPIO In Set-up Time)	10	10		ns
204	EXTAL Edge to GPIO In Not Valid (GPIO In Hold Time)	6	6		ns



AA0276

Figure 2-22 GPIO Timing

On-Chip Emulation (OnCETM) Timing

ON-CHIP EMULATION (OnCETM) TIMING

 $(C_L = 50 \text{ pF} + 2 \text{ TTL Loads})$

No.	Characteristics	50/66/8	Unit		
110.		Min	Max		
230	DSCK Low	40	_	ns	
231	DSCK High	40	_	ns	
232	DSCK Cycle Time	200	_	ns	
233	$\overline{\text{DR}}$ Asserted to DSO ($\overline{\text{ACK}}$) Asserted	5 T _C	_	ns	
234	DSCK High to DSO Valid	_	42	ns	
235	DSCK High to DSO Invalid	3		ns	
236	DSI Valid to DSCK Low (Set-up)	15		ns	
237	DSCK Low to DSI Invalid (Hold) 3			ns	
238	Last DSCK Low to OS0-OS1, ACK Active	$3 T_{C} + T_{L}$		ns	
239	DSO (ACK) Asserted to First DSCK High	2 T _C		ns	
240	DSO (ACK) Assertion Width	$4 T_{\rm C} + T_{\rm H} - 3$	5 T _C + 7	ns	
241	DSO (ACK) Asserted to OS0–OS1 High Impedance ¹	_	0	ns	
242	OS0-OS1 Valid to EXTAL Transition #2	T _C – 21	_	ns	
243	EXTAL Transition #2 to OS0-OS1 Invalid	0		ns	
244	Last DSCK Low of Read Register to First DSCK High of Next Command	7 T _C + 10 —		ns	
245	Last DSCK Low to DSO Invalid (Hold)	3	_	ns	
246	DR Assertion to EXTAL Transition #2 for Wake Up from WAIT State	10 T _C - 10		ns	
247	EXTAL Transition #2 to DSO After Wake Up from WAIT State	17 T _C		ns	

NL		50/66/8		
No.	Characteristics	Min	Max	Unit
248	 DR Assertion Width to recover from WAIT to recover from WAIT and enter Debug mode 	15 13 T _C + 15	12 T _C - 15 	ns ns
249	DR Assertion to DSO (ACK) Valid (Enter Debug mode) After Asynchronous Recovery from WAIT State	17 T _C		ns
250A	 DR Assertion Width to Recover from STOP² Stable External Clock, OMR Bit 6 = 0 Stable External Clock, OMR Bit 6 = 1 Stable External Clock, PCTL Bit 17 = 1 	15 15 15	$\begin{array}{c} 65548\ T_{C}+T_{L}\\ 20\ T_{C}+T_{L}\\ 13\ T_{C}+T_{L} \end{array}$	ns ns ns
250B	 DR Assertion Width to Recover from STOP and enter Debug mode² Stable External Clock, OMR Bit 6 = 0 Stable External Clock, OMR Bit 6 = 1 Stable External Clock, PCTL Bit 17 = 1 	$\begin{array}{c} 65549\ T_{C}+T_{L}\\ 21\ T_{C}+T_{L}\\ 14\ T_{C}+T_{L} \end{array}$		ns ns ns
251	 DR Assertion to DSO (ACK) Valid (Enter Debug mode) After Recovery from STOP State² Stable External Clock, OMR Bit 6 = 0 Stable External Clock, OMR Bit 6 = 1 Stable External Clock, PCTL Bit 17 = 1 	$\begin{array}{c} 65553\ T_{C}+T_{L}\\ 25\ T_{C}+T_{L}\\ 18\ T_{C}+T_{L} \end{array}$		ns ns ns
Note:	 Maximum T_L Periodically sampled, not 100% tested 	1	1	<u> </u>

 Table 2-17
 OnCE Timing (Continued)

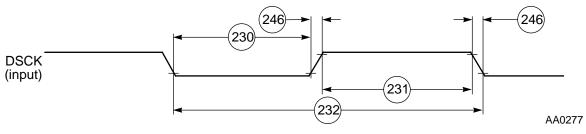
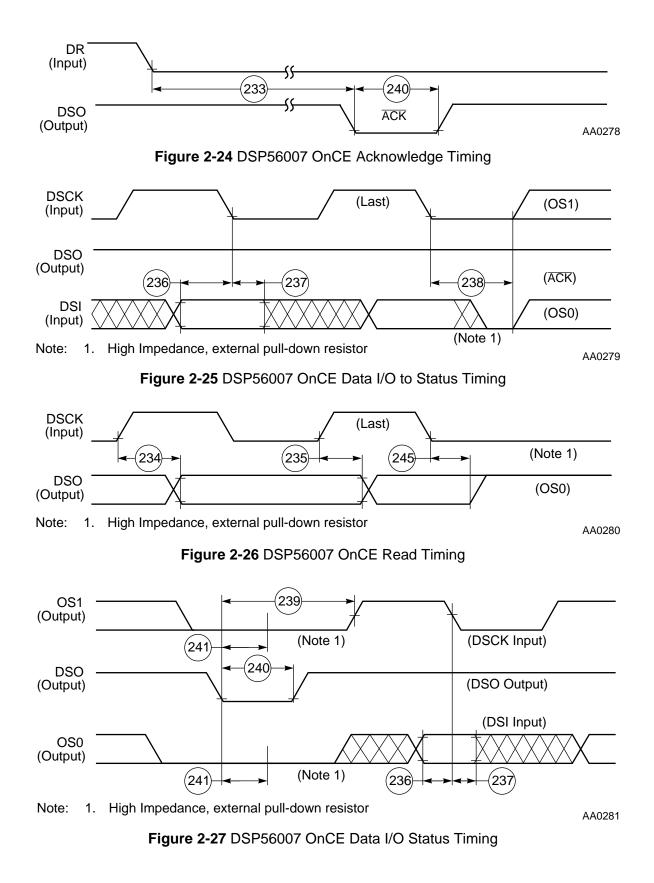


Figure 2-23 DSP56007 OnCE Serial Clock Timing

DSP56007/D



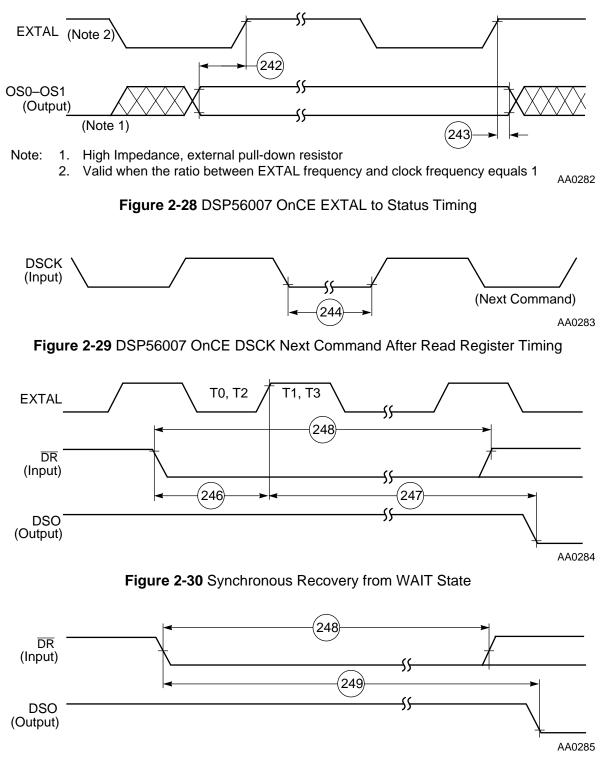


Figure 2-31 Asynchronous Recovery from WAIT State

On-Chip Emulation (OnCETM) Timing

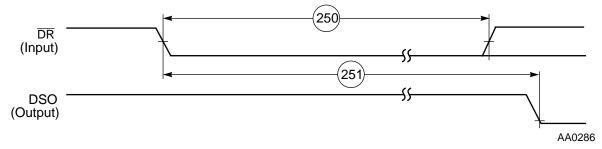


Figure 2-32 Asynchronous Recovery from STOP State

SECTION 3

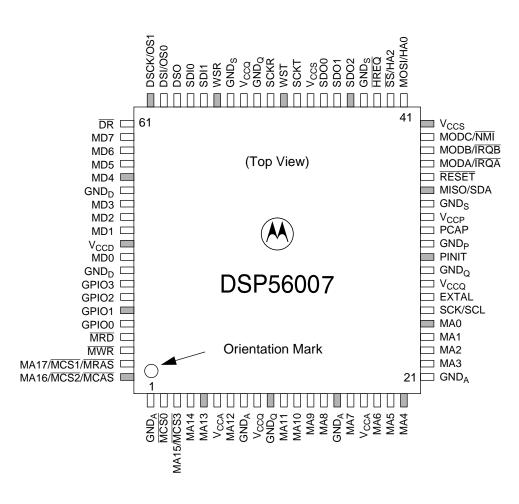
PACKAGING

PIN-OUT AND PACKAGE INFORMATION

This section provides information about the available packages for this product, including diagrams of the package pinouts and tables describing how the signals described in **Section 1** are allocated. The DSP56007 is available in an 80-pin Quad Flat Pack (QFP) package.

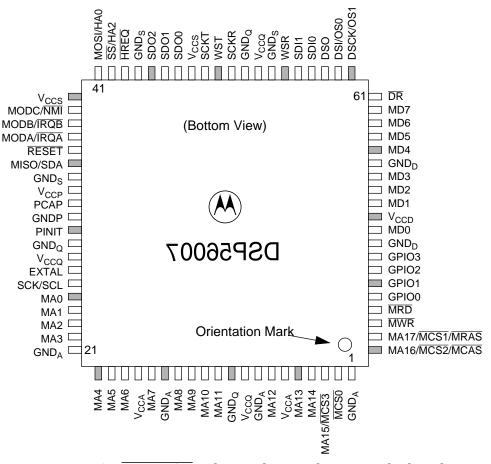
QFP Package Description

Top and bottom views of the QFP package are shown in **Figure 3-1** and **Figure 3-2** with their pin-outs.



Note: An OVERBAR indicates the signal is asserted when the voltage = ground (active low). To simplify locating the pins, each fifth pin is shaded in the illustration.

Figure 3-1 Top View



Note: An OVERBAR indicates the signal is asserted when the voltage = ground (active low). To simplify locating the pins, each fifth pin is shaded in the illustration.

Figure 3-2 Bottom View

Pin #	Signal Name	Pin #	Signal Name	Pin #	Signal Name
1	GNDA	28	V _{CCQ}	55	WSR
2	MCSO	29	GNDQ	56	SDI1
3	MA15/MCS3	30	PINIT	57	SDI0
4	MA14	31	GND _P	58	DSO
5	MA13	32	PCAP	59	DSI/OS0
6	V _{CCA}	33	V _{CCP}	60	DSCK/OS1
7	MA12	34	GND _S	61	DR
8	GNDA	35	MISO/SDA	62	MD7
9	V _{CCQ}	36	RESET	63	MD6
10	GND _Q	37	MODA/IRQA	64	MD5
11	MA11	38	MODB/IRQB	65	MD4
12	MA10	39	MODC/NMI	66	GND _D
13	MA9	40	V _{CCS}	67	MD3
14	MA8	41	MOSI/HA0	68	MD2
15	GNDA	42	SS/HA2	69	MD1
16	MA7	43	HREQ	70	V _{CCD}
17	V _{CCA}	44	GND _S	71	MD0
18	MA6	45	SDO2	72	GND _D
19	MA5	46	SDO1	73	GPIO3
20	MA4	47	SDO0	74	GPIO2
21	GNDA	48	V _{CCS}	75	GPIO1
22	MA3	49	SCKT	76	GPIO0
23	MA2	50	WST	77	MRD
24	MA1	51	SCKR	78	MWR
25	MA0	52	GND _Q	79	MA17/MCS1/ MRAS
26	SCK/SCL	53	V _{CCQ}	80	MA16/MCS2/ MCAS
27	EXTAL	54	GND _S		

 Table 3-1
 DSP56007 Pin Identification by Pin Number

Signal Name	Pin #	Signal Name	Pin #	Signal Name	Pin #
DR	61	MA5	19	MRD	77
DSCK	60	MA6	18	MWR	78
DSI	59	MA7	16	NMI	39
DSO	58	MA8	14	OS0	59
EXTAL	27	MA9	13	OS1	60
GNDA	1	MA10	12	PCAP	32
GNDA	8	MA11	11	PINIT	30
GNDA	15	MA12	7	RESET	36
GNDA	21	MA13	5	SCK	26
GND _D	66	MA14	4	SCKR	51
GND _D	72	MA15	3	SCKT	49
GND _P	31	MA16	80	SCL	26
GND _Q	10	MA17	79	SDA	35
GNDQ	29	MCAS	80	SDI0	57
GND_Q	52	MCS0	2	SDI1	56
GND _S	34	MCS1	79	SDO0	47
GND _S	44	MCS2	80	SDO1	46
GND _S	54	MCS3	3	SDO2	45
GPIO0	76	MD0	71	<u>SS</u>	42
GPIO1	75	MD1	69	V _{CCA}	6
GPIO2	74	MD2	68	V _{CCA}	17
GPIO3	73	MD3	67	V _{CCD}	70
HA0	41	MD4	65	V _{CCP}	33
HA2	42	MD5	64	V _{CCQ}	9
HREQ	43	MD6	63	V _{CCQ}	28
ĪRQĀ	37	MD7	62	V_{CCQ}	53
ĪRQB	38	MISO	35	V _{CCS}	40
MA0	25	MODA	37	V _{CCS}	48
MA1	24	MODB	38	WSR	55
MA2	23	MODC	39	WST	50
MA3	22	MOSI	41		
MA4	20	MRAS	79		

 Table 3-2
 DSP56007 Pin Identification by Signal Name

Pin #	Signal Name	Circuit Supplied
6	V _{CCA}	Address Bus Buffers
17		
1	GND _A	
8		
15		
21		
70	V _{CCD}	Data Bus Buffers
66	GND _D	
72		
9	V _{CCQ}	Internal Logic
28		
53		
10	GND _Q	
29	_	
52		
33	V _{CCP}	PLL
31	GND _P	
40	V _{CCS}	Serial Ports
48		
34	GND _S	
44		
54		

Table 3-3DSP56007 Power Supply Pins

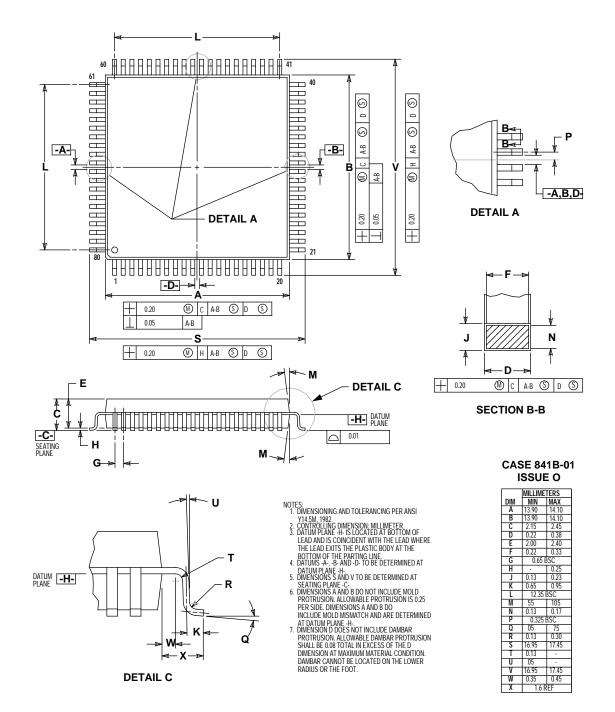
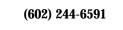


Figure 3-3 80-pin Quad Flat Pack (QFP) Mechanical Information

ORDERING DRAWINGS

Complete mechanical information regarding DSP56007 packaging is available by facsimile through Motorola's Mfax[™] system. Call the following number to obtain information by facsimile:



The Mfax automated system requests the following information:

- The receiving facsimile telephone number including area code or country code
- The caller's Personal Identification Number (PIN)
- **Note:** For first time callers, the system provides instructions for setting up a PIN, which requires entry of a name and telephone number.
 - The type of information requested:
 - Instructions for using the system
 - A literature order form
 - Specific part technical information or data sheets
 - Other information described by the system messages

A total of three documents may be ordered per call.

The DSP56007 80-pin QFP package mechanical drawing is referenced as 841B-01.

dsp

SECTION 4

DESIGN CONSIDERATIONS

THERMAL DESIGN CONSIDERATIONS

An estimation of the chip junction temperature, T_J , in °C can be obtained from the equation:

Equation 1: $T_J = T_A + (P_D \times R_{\theta JA})$

Where:

 T_A = ambient temperature °C R_{0JA} = package junction-to-ambient thermal resistance °C/W P_D = power dissipation in package

Historically, thermal resistance has been expressed as the sum of a junction-to-case thermal resistance and a case-to-ambient thermal resistance:

Equation 2: $R_{\theta JA} = R_{\theta JC} + R_{\theta CA}$

Where:

$$\begin{split} R_{\theta JA} &= package \ junction-to-ambient \ thermal \ resistance \ ^{C}/W \\ R_{\theta JC} &= package \ junction-to-case \ thermal \ resistance \ ^{C}/W \\ R_{\theta CA} &= package \ case-to-ambient \ thermal \ resistance \ ^{C}/W \end{split}$$

 $R_{\theta JC}$ is device-related and cannot be influenced by the user. The user controls the thermal environment to change the case-to-ambient thermal resistance, $R_{\theta CA}$. For example, the user can change the air flow around the device, add a heat sink, change the mounting arrangement on the Printed Circuit Board (PCB), or otherwise change the thermal dissipation capability of the area surrounding the device on a PCB. This model is most useful for ceramic packages with heat sinks; some 90% of the heat flow is dissipated through the case to the heat sink and out to the ambient environment. For ceramic packages, in situations where the heat flow is split between a path to the case and an alternate path through the PCB, analysis of the device thermal performance may need the additional modeling capability of a system level thermal simulation tool.

Thermal Design Considerations

The thermal performance of plastic packages is more dependent on the temperature of the PCB to which the package is mounted. Again, if the estimations obtained from $R_{\theta JA}$ do not satisfactorily answer whether the thermal performance is adequate, a system level model may be appropriate.

A complicating factor is the existence of three common ways for determining the junction-to-case thermal resistance in plastic packages:

- To minimize temperature variation across the surface, the thermal resistance is measured from the junction to the outside surface of the package (case) closest to the chip mounting area when that surface has a proper heat sink.
- To define a value approximately equal to a junction-to-board thermal resistance, the thermal resistance is measured from the junction to where the leads are attached to the case.
- If the temperature of the package case (T_T) is determined by a thermocouple, the thermal resistance is computed using the value obtained by the equation $(T_J T_T)/P_D$.

As noted above, the junction-to-case thermal resistances quoted in this data sheet are determined using the first definition. From a practical standpoint, that value is also suitable for determining the junction temperature from a case thermocouple reading in forced convection environments. In natural convection, using the junction-to-case thermal resistance to estimate junction temperature from a thermocouple reading on the case of the package will estimate a junction temperature slightly hotter than actual temperature. Hence, the new thermal metric, Thermal Characterization Parameter or Ψ_{JT} , has been defined to be $(T_J - T_T)/P_D$. This value gives a better estimate of the junction temperature in natural convection when using the surface temperature of the package. Remember that surface temperature readings of packages are subject to significant errors caused by inadequate attachment of the sensor to the surface and to errors caused by heat loss to the sensor. The recommended technique is to attach a 40-gauge thermocouple wire and bead to the top center of the package with thermally conductive epoxy.

ELECTRICAL DESIGN CONSIDERATIONS

CAUTION

This device contains protective circuitry to guard against damage due to high static voltage or electrical fields. However, normal precautions are advised to avoid application of any voltages higher than maximum rated voltages to this high-impedance circuit. Reliability of operation is enhanced if unused inputs are tied to an appropriate logic voltage level (e.g., either GND or V_{CC}).

Use the following list of recommendations to assure correct DSP operation:

- Provide a low-impedance path from the board power supply to each V_{CC} pin on the DSP, and from the board ground to each GND pin.
- Use at least four 0.01–0.1 μF bypass capacitors positioned as close as possible to the four sides of the package to connect the V_{CC} power source to GND.
- Ensure that capacitor leads and associated printed circuit traces that connect to the chip V_{CC} and GND pins are less than 0.5 in per capacitor lead.
- Use at least a four-layer Printed Circuit Board (PCB) with two inner layers for V_{CC} and GND.
- Because the DSP output signals have fast rise and fall times, PCB trace lengths should be minimal. This recommendation particularly applies to the address and data buses as well as the IRQA, IRQB, and NMI pins. Maximum Printed Circuit Board (PCB) trace lengths on the order of 6 inches are recommended.
- Consider all device loads as well as parasitic capacitance due to PCB traces when calculating capacitance. This is especially critical in systems with higher capacitive loads that could create higher transient currents in the V_{CC} and GND circuits.
- All inputs must be terminated (i.e., not allowed to float) using CMOS levels, except as noted in **Section 1**.
- Take special care to minimize noise levels on the V_{CCP} and GND_P pins.
- If multiple DSP56007 devices are on the same board, check for cross-talk or excessive spikes on the supplies due to synchronous operation of the devices.

Power Consumption Considerations

POWER CONSUMPTION CONSIDERATIONS

Power dissipation is a key issue in portable DSP applications. Some of the factors which affect current consumption are described in this section. Most of the current consumed by CMOS devices is Alternating Current (AC), which is charging and discharging the capacitances of the pins and internal nodes.

Current consumption is described by the formula:

Equation 3: $I = C \times V \times f$

where: C = node/pin capacitance in farads V = voltage swing f = frequency of node/pin toggle in hertz

Example 4-1 Current Consumption

For an I/O pin loaded with 50 pF capacitance, operating at 5.25 V, and with a 88 MHz clock, toggling at its maximum possible rate (22 MHz), the current consumption is:

Equation 4: I = $50 \times 10^{-12} \times 5.25 \times 22 \times 10^{6} = 5.78 \text{ mA}$

The Maximum Internal Current (I_{CCI} max) value reflects the typical possible switching of the internal buses on best-case operation conditions, which is not necessarily a real application case. The Typical Internal Current (I_{CCItyp}) value reflects the average switching of the internal buses on typical operating conditions.

For applications that require very low current consumption:

- Minimize the number of pins that are switching.
- Minimize the capacitive load on the pins.
- Connect the unused inputs to pull-up or pull-down resistors.
- Disable unused peripherals.
- Disable unused pin activity.

Power Consumption Considerations

Current consumption test code:

jmp MAIN	
org p:MAIN	
movep #\$180000,x:\$FFFD	
move #0,r0	
move #0,r4	
move #\$00FF,m0	
move #\$00FF,m4	
nop	
rep #256	
move r0,x:(r0)+	
rep #256	
mov r4,y:(r4)+	
clr a	
move l:(r0)+,a	
rep #30	
<pre>mac x0,y0,a x:(r0)+,x0</pre>	y:(r4)+,y0
move a,p:(r5)	
jmp TP1	
TP1 nop	
jmp MAIN	

Power-Up Considerations

POWER-UP CONSIDERATIONS

To power-up the device properly, ensure that the following conditions are met:

- Stable power is applied to the device according to the specifications in **Table 2-3** (DC Electrical Characteristics).
- The external clock oscillator is active and stable.
- **RESET** is asserted according to the specifications in **Table 2-7** (Reset, Stop, Mode Select, and Interrupt Timing).
- The following input pins are driven to valid voltage levels: DR, PINIT, MODA, MODB, and MODC.

Care should be taken to ensure that the maximum ratings for all input voltages obey the restrictions on **Table 2-1** (Maximum Ratings), at all phases of the power-up procedure. This may be achieved by powering the external clock, hardware reset, and mode selection circuits from the same power supply that is connected to the power supply pins of the chip.

At the beginning of the hardware reset procedure, the device might consume significantly more current than the specified typical supply current. This is because of contentions among the internal nodes being affected by the hardware reset signal until they reach their final hardware reset state.

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SECTION 5

ORDERING INFORMATION

Consult a Motorola Semiconductor sales office or authorized distributor to determine product availability and to place an order.

Part	Supply Voltage	Package Type	Pin Count	Frequency (MHz)	Order Number
DSPB56007 ¹	5 V	Quad Flat Pack (QFP)	80	50	DSPB56007FJ50
				66	DSPB56007FJ66
				88	DSPB56007FJ88
DSPE56007 ²	5 V	Quad Flat Pack (QFP)	80	50	DSPE56007FJ50
				66	DSPE56007FJ66
				88	DSPE56007FJ88
 Note: 1. The DSPB56007 includes a generic factory-programmed ROM and may be used for RAM-based applications. For additional information on future part development, or to request specific ROM-based support, call your local Motorola Semiconductor sales office or authorized distributor. 2. The DSPE56007 includes factory-programmed ROM containing support for Dolby Pro Logic and Lucasfilm THX applications. This part can be used only be customers licensed for Dolby Pro Logic and Lucasfilm THX. To request specific support for this chip, call your local Motorola Semiconductor sales office or authorized distributor. 					

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